To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

Send any inquiries to http://www.renesas.com/inquiry.

RENESAS

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.

2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.

3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.

4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.

5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.

6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.

7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

    "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

    "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

    "Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.

8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.

9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.

10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.

11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.

12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

To all our customers

Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Renesas Technology Corp.

DESCRIPTION

The 38C8 group is the 8-bit microcomputer based on the 740 family core technology.

The 38C8 group has a LCD drive control circuit (bias control, time sharing control), a 10-bit A-D converter, and a Serial I/O as additional functions.

The various microcomputers in the 38C8 group include variations of internal memory type and packaging. For details, refer to the section on part numbering.

FEATURES

- Basic machine-language instructions 71
- The minimum instruction execution time .... 0.5 μs
  (at 8 MHz oscillation frequency)
- Memory size
  ROM .... 60 K bytes
  RAM .... 2048 bytes
- Programmable input/output ports 35
- Software pull-up resistors
  .... Ports P0–P3, P4$_1$–P4$_7$
- Interrupts .... 14 sources, 14 vectors
  (includes key input interrupt)
- Timers .... 8-bit ✕ 3, 16-bit ✕ 2
- Serial I/O .... 8-bit ✕ 1 (UART or Clock-synchronized)
- A-D converter (32 kHz operating available) ... 10-bit ✕ 8 channels

- LCD drive control circuit
  Bias 1/5, 1/7
  Duty 1/16, 1/32
  Common output .... 16 or 32
  Segment output .... 52 or 68
- Main clock generating circuit (RC oscillation selectable)
  .... (connect to external ceramic resonator or resistor)
- Sub-clock generating circuit
  .... (connect to external quartz-crystal oscilaltor)
- Power source voltage
  In high-speed mode .... 4.0 to 5.5 V
  In middle-speed mode .... 2.2 to 5.5 V
  In low-speed mode .... 2.2 to 5.5 V
- Power dissipation
  In high-speed mode .... 30 mW
    (at 8 MHz oscillation frequency, at 5 V power source voltage)
  In low-speed mode .... 60 μW
    (at 32 kHz oscillation frequency, at 3 V power source voltage, at WIT state, at voltage multiplier operating, LCD drive waveform generating state)
- Operating temperature range .... − 20 to 85°C

APPLICATIONS

Dot-matrix-type LCD displays

PIN CONFIGURATION (TOP VIEW)
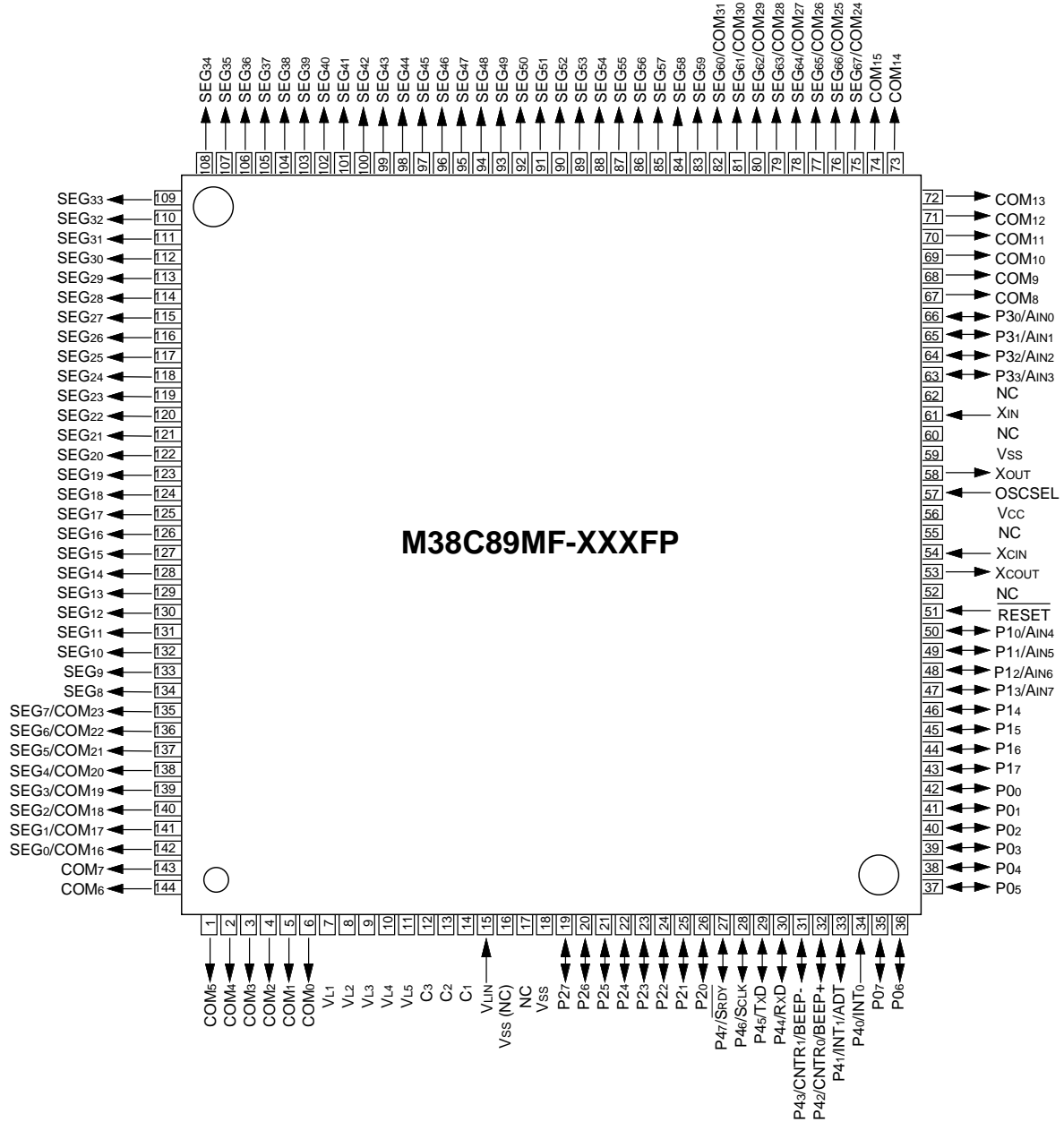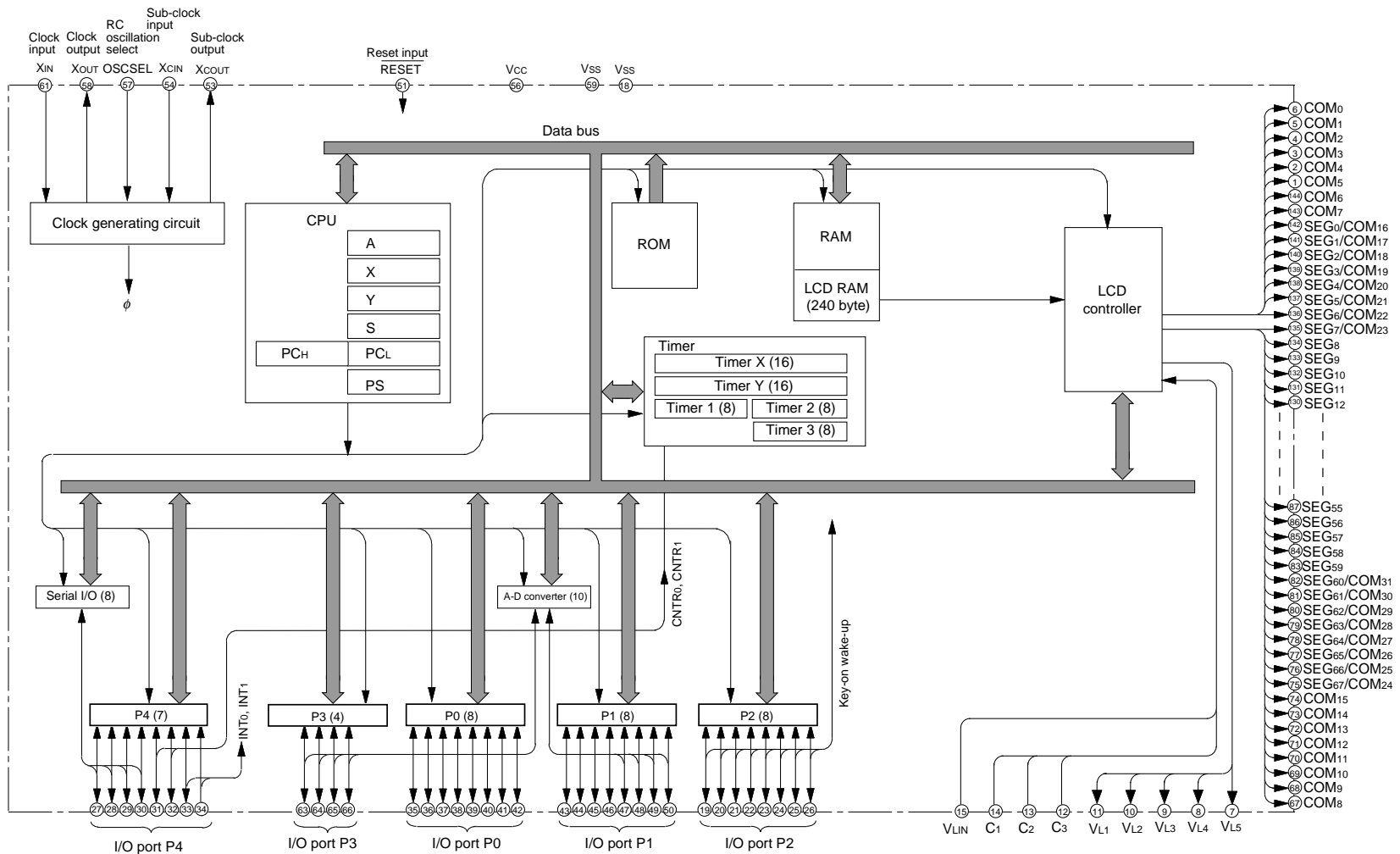

M38C89MF-XXXFP

Package type : 144P6Q-A

Fig. 1 M38C89MF-XXXFP pin configuration

Fig. 2 Functional block diagram

Fig. 2

FUNCTIONAL BLOCK DIAGRAM (Package: 144P6Q-A)

PIN DESCRIPTION

Table 1 Pin description

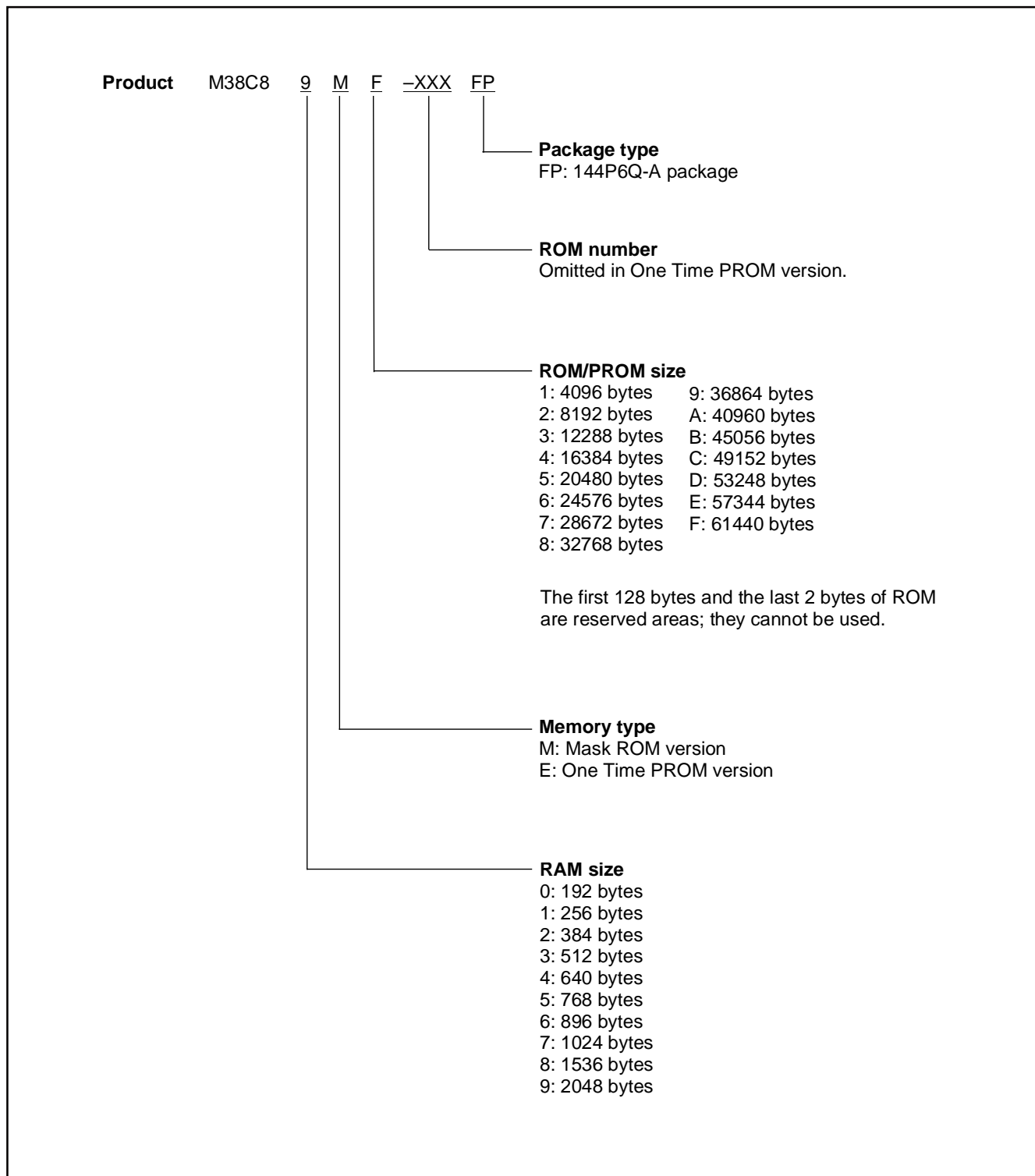| Pin	Name	Function	Function except a port function
V_{CC}, V_{SS}	Power source	• Apply voltage of 4.0–5.5 V to V_{CC}, and 0 V to V_{SS}. (at high-speed mode)	
$\overline{RESET}$	Reset input	• Reset input pin for active "L."	
X_{IN}	Clock input	• Input and output pins for the main clock generating circuit. • Feedback resistor is built in between X_{IN} pin and X_{OUT} pin.	
X_{OUT}	Clock output	• Connect a ceramic resonator or a quartz-crystal oscillator between the X_{IN} and X_{OUT} pins to set the oscillation frequency. • If an external clock is used, connect the clock source to the X_{IN} pin and leave the X_{OUT} pin open.	
OSCSEL	RC oscillation select	• This pin determines the oscillation between X_{IN} and X_{OUT}. The oscillation method can be selected from either by an oscillator or by a resistor.	
X_{CIN}	Sub-clock input	• Input and output pins for sub-clock generating circuit. (Connect a quartz-crystal oscillator between the X_{CIN} and X_{COUT} pins to set the oscillation frequency. The clock generated the externals cannot be input directly.)	
X_{COUT}	Sub-clock output		
V_{LIN}	Power source input for LCD	• Reference voltage input pin for LCD. • The input voltage to this pin is boosted threefold by voltage multiplier.	
$V_{L1} - V_{L5}$	LCD power source	• LCD drive power source pins.	
$COM_0 - COM_{15}$	Common output	• LCD common output pins.	
SEG_0/COM_{16}–SEG_7/COM_{23}, $SEG_{60}COM_{31}$–SEG_{67}/COM_{24}	Segment output/ Common output	• LCD segment/common output pins.	
SEG_8–SEG_{59}	Segment output	• LCD segment output pins.	
$P0_0$–$P0_7$	I/O port P0	• 8-bit I/O port.	
$P1_4$–$P1_7$	I/O port P1	• CMOS compatible input level.	
$P1_0/AIN_4$–$P1_3/AIN_7$		• CMOS 3-state output structure.	• A-D converter analog input pin
$P2_0$–$P2_7$	I/O port P2		• Key-on wake-up interrupt input pin
$P3_0/AIN_0 - P3_3/AIN_3$	I/O port P3	• 4-bit I/O port. • CMOS compatible input level. • CMOS 3-state output structure.	• A-D converter analog input pin
$P4_0/INT_0$	Input port P4	• 1-bit input port. • CMOS compatible input level.	• External interrupt pin
$P4_1/INT_1/ADT$	I/O port P4	• 7-bit I/O port. • CMOS compatible input level.	• External interrupt pin • A-D trigger input pin
$P4_2/CNTR_0/$ BEEP+, $P4_3/CNTR_1/$ BEEP-		• CMOS 3-state output structure. • I/O direction register allows each pin to be individually programmed as either input or output.	•Timer function I/O pin
$P4_4/RxD$, $P4_5/TxD$, $P4_6/S_{CLK}$, $P4_7/S_{RDY}$			• Serial I/O I/O pin
C_1, C_2, C_3	Voltage multiplier	• External capacitor connect pins for a voltage multiplier of LCD.	
V_{SS} (NC), NC		• Non-function pins. • Leave the V_{SS} (NC) pin open.	

RENESAS
Renesas Technology Corp.

PART NUMBERING

Product   M38C8   9   M   F   –XXX   FP

Package type
FP: 144P6Q-A package

ROM number
Omitted in One Time PROM version.

ROM/PROM size

1: 4096 bytes	9: 36864 bytes
2: 8192 bytes	A: 40960 bytes
3: 12288 bytes	B: 45056 bytes
4: 16384 bytes	C: 49152 bytes
5: 20480 bytes	D: 53248 bytes
6: 24576 bytes	E: 57344 bytes
7: 28672 bytes	F: 61440 bytes
8: 32768 bytes	

The first 128 bytes and the last 2 bytes of ROM are reserved areas; they cannot be used.

Memory type
M: Mask ROM version
E: One Time PROM version

RAM size
0: 192 bytes
1: 256 bytes
2: 384 bytes
3: 512 bytes
4: 640 bytes
5: 768 bytes
6: 896 bytes
7: 1024 bytes
8: 1536 bytes
9: 2048 bytes

Fig. 3 Part numbering

GROUP EXPANSION

Mitsubishi plans to expand the 38C8 group as follows.

Memory Type

Support for mask ROM and One Time PROM versions

Memory Size

ROM/PROM size .... 60 K bytes
RAM size .... 2048 bytes

Packages

144P6Q-A .... 0.5 mm-pitch plastic molded QFP

Memory Expansion Plan

ROM size (bytes)

M38C89MF/EF
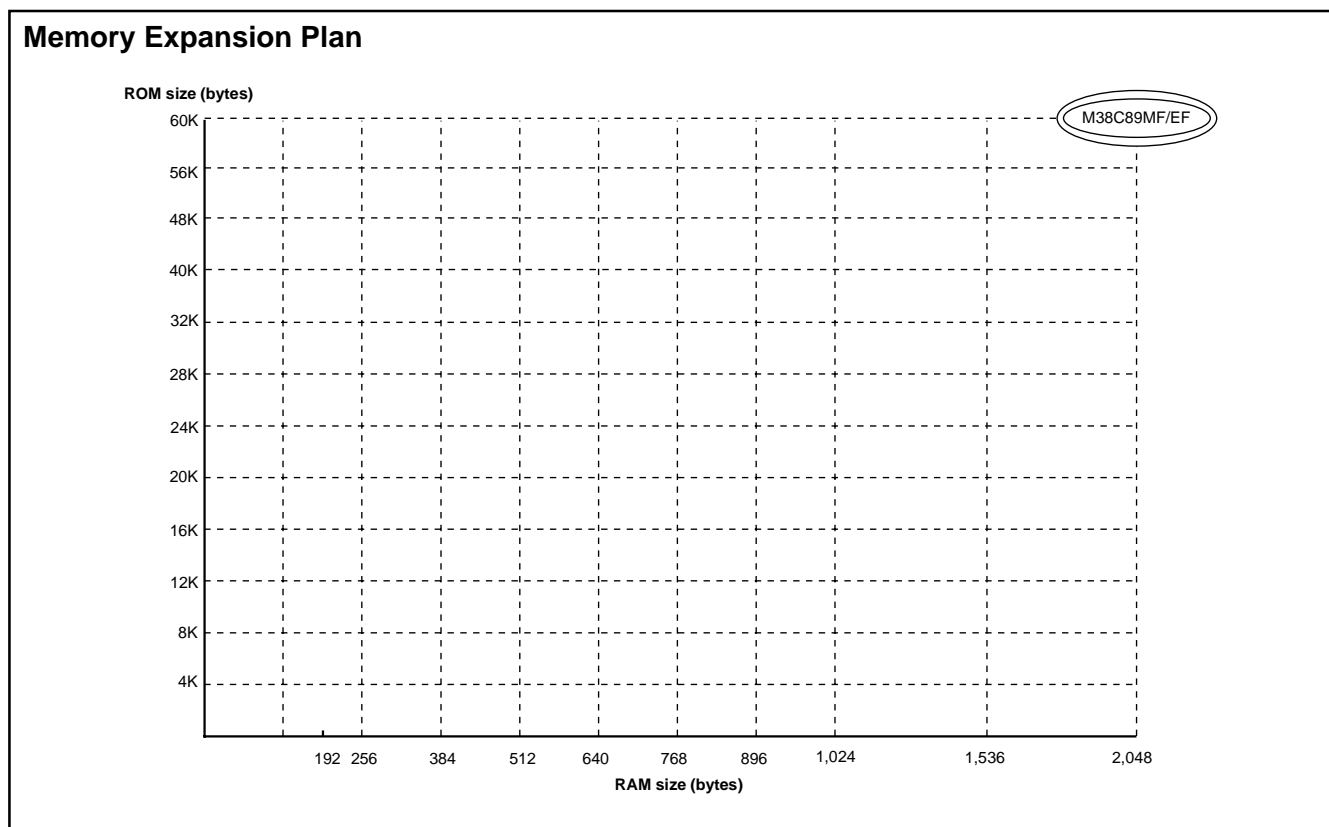
RAM size (bytes)

Fig. 4 Memory expansion plan

Currently products are listed below.

Table 2 List of products

Product name	(P) ROM size (bytes) ROM size for User in ( )	RAM size (bytes)	Package	Remarks
M38C89MF-XXXFP	61440 (61310)	2048	144P6Q-A	Mask ROM version
M38C89EFFP	61440 (61310)	2048	144P6Q-A	One Time PROM version

RENESAS
RenesasTechnology Corp.

FUNCTIONAL DESCRIPTION
CENTRAL PROCESSING UNIT (CPU)

The 38C8 group uses the standard 740 family instruction set. Refer to the table of 740 family addressing modes and machine instructions or the 740 Family Software Manual for details on the instruction set.

Machine-resident 740 family instructions are as follows:

The FST and SLW instruction cannot be used.

The STP, WIT, MUL, and DIV instruction can be used.

[Accumulator (A)]

The accumulator is an 8-bit register. Data operations such as data transfer, etc., are executed mainly through the accumulator.

[Index Register X (X)]

The index register X is an 8-bit register. In the index addressing modes, the value of the OPERAND is added to the contents of register X and specifies the real address.

[Index Register Y (Y)]

The index register Y is an 8-bit register. In partial instruction, the value of the OPERAND is added to the contents of register Y and specifies the real address.

[Stack Pointer (S)]

The stack pointer is an 8-bit register used during subroutine calls and interrupts. This register indicates start address of stored area (stack) for storing registers during subroutine calls and interrupts.

The low-order 8 bits of the stack address are determined by the contents of the stack pointer. The high-order 8 bits of the stack address are determined by the stack page selection bit. If the stack page selection bit is "0" , the high-order 8 bits becomes "00_{16}". If the stack page selection bit is "1", the high-order 8 bits becomes "01_{16}".

The operations of pushing register contents onto the stack and popping them from the stack are shown in Figure 6.

Store registers other than those described in Figure 6 with program when the user needs them during interrupts or subroutine calls.

[Program Counter (PC)]

The program counter is a 16-bit counter consisting of two 8-bit registers PC_H and PC_L. It is used to indicate the address of the next instruction to be executed.
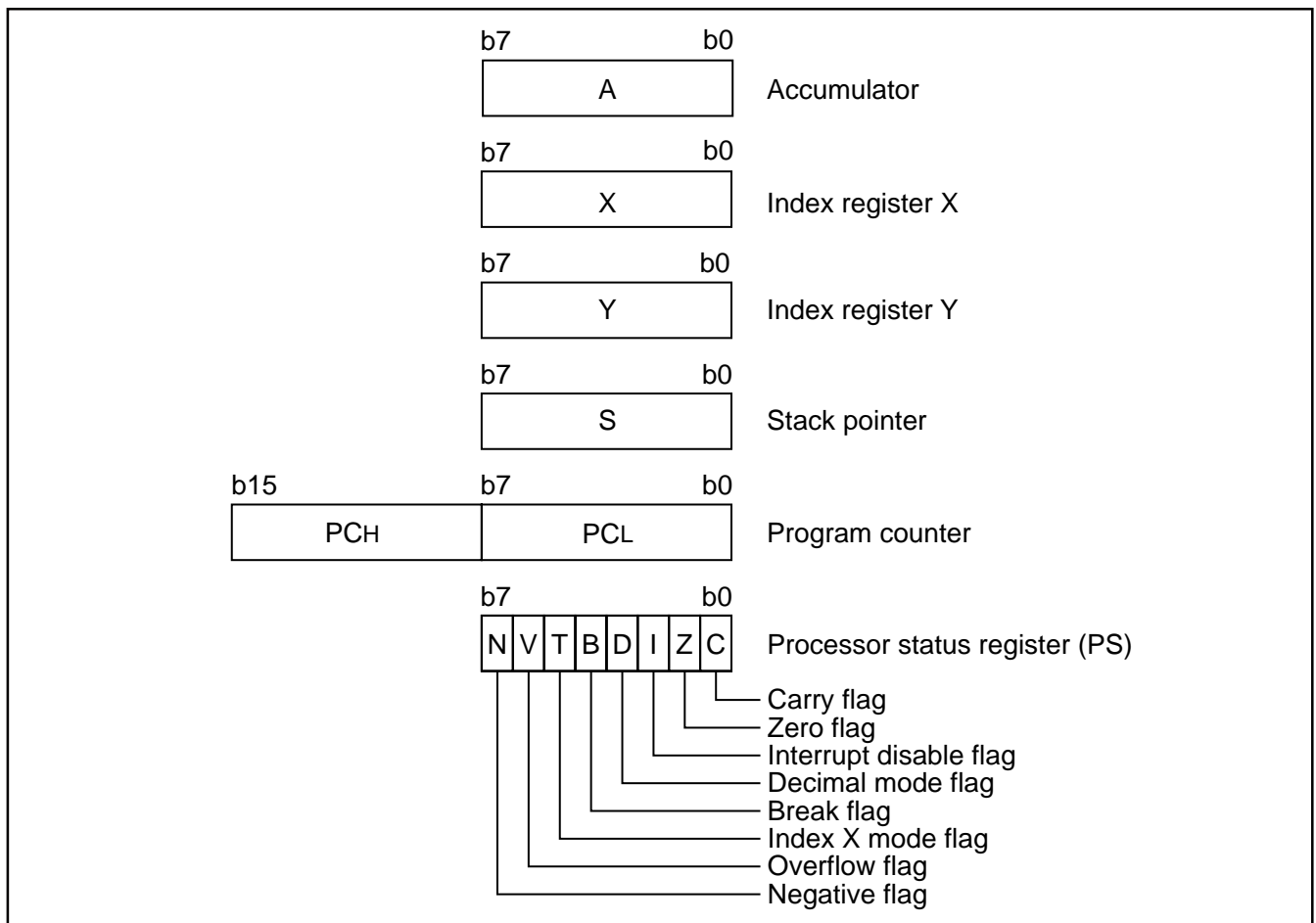

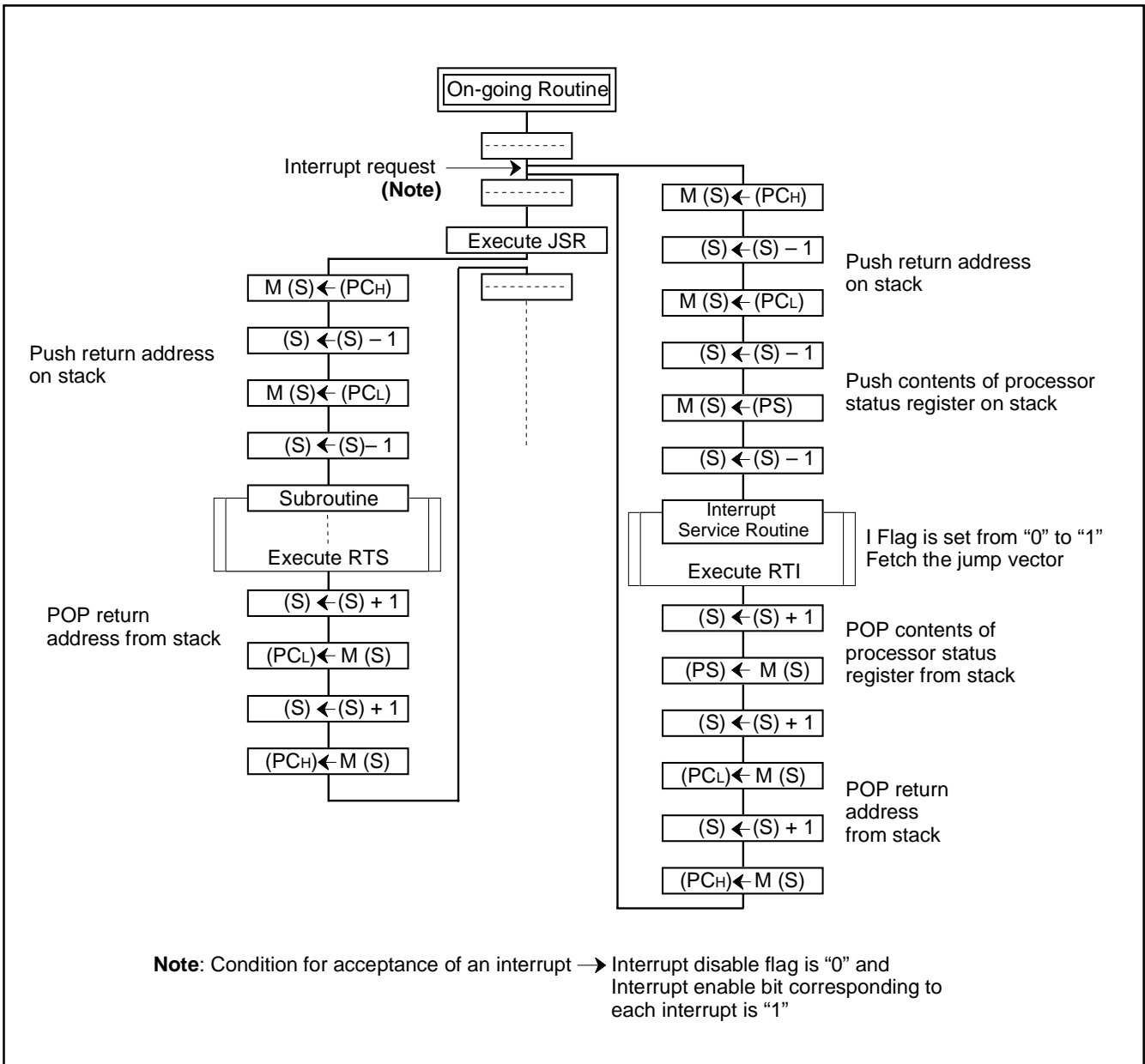**Fig. 5 740 Family CPU register structure**

Fig. 6 Register push and pop at interrupt generation and subroutine call

Table 3 Push and pop instructions of accumulator or processor status register

	Push instruction to stack	Pop instruction from stack
Accumulator	PHA	PLA
Processor status register	PHP	PLP

[Processor status register (PS)]

The processor status register is an 8-bit register consisting of 5 flags which indicate the status of the processor after an arithmetic operation and 3 flags which decide MCU operation. Branch operations can be performed by testing the Carry (C) flag , Zero (Z) flag, Overflow (V) flag, or the Negative (N) flag. In decimal mode, the Z, V, N flags are not valid.

- Bit 0: Carry flag (C)

    The C flag contains a carry or borrow generated by the arithmetic logic unit (ALU) immediately after an arithmetic operation. It can also be changed by a shift or rotate instruction.
- Bit 1: Zero flag (Z)

    The Z flag is set if the result of an immediate arithmetic operation or a data transfer is "0", and cleared if the result is anything other than "0".
- Bit 2: Interrupt disable flag (I)

    The I flag disables all interrupts except for the interrupt generated by the BRK instruction.

    Interrupts are disabled when the I flag is "1".
- Bit 3: Decimal mode flag (D)

    The D flag determines whether additions and subtractions are executed in binary or decimal. Binary arithmetic is executed when this flag is "0"; decimal arithmetic is executed when it is "1". Decimal correction is automatic in decimal mode. Only the ADC and SBC instructions can be used for decimal arithmetic.

- Bit 4: Break flag (B)

    The B flag is used to indicate that the current interrupt was generated by the BRK instruction. The BRK flag in the processor status register is always "0". When the BRK instruction is used to generate an interrupt, the processor status register is pushed onto the stack with the break flag set to "1".
- Bit 5: Index X mode flag (T)

    When the T flag is "0", arithmetic operations are performed between accumulator and memory. When the T flag is "1", direct arithmetic operations and direct data transfers are enabled between memory locations.
- Bit 6: Overflow flag (V)

    The V flag is used during the addition or subtraction of one byte of signed data. It is set if the result exceeds +127 to -128. When the BIT instruction is executed, bit 6 of the memory location operated on by the BIT instruction is stored in the overflow flag.
- Bit 7: Negative flag (N)

    The N flag is set if the result of an arithmetic operation or data transfer is negative. When the BIT instruction is executed, bit 7 of the memory location operated on by the BIT instruction is stored in the negative flag.

Table 4 Set and clear instructions of each bit of processor status register

	C flag	Z flag	I flag	D flag	B flag	T flag	V flag	N flag
Set instruction	SEC	–	SEI	SED	–	SET	–	–
Clear instruction	CLC	–	CLI	CLD	–	CLT	CLV	–

[CPU Mode Register (CPUM)] 003B16

The CPU mode register contains the stack page selection bit and the internal system clock selection bit.

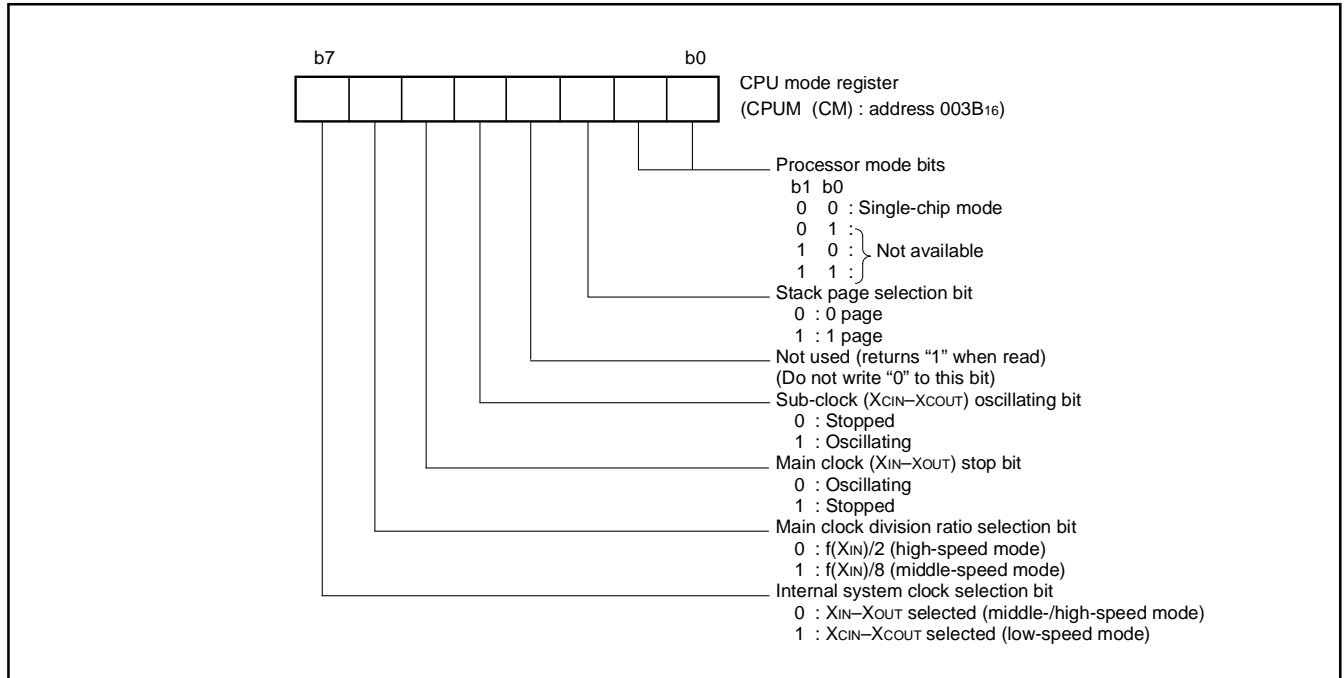The CPU mode register is allocated at address 003B16.

b7   b0

CPU mode register
(CPUM (CM) : address 003B16)

Processor mode bits
b1 b0
0 0 : Single-chip mode
0 1 : ⎫
1 0 : ⎬ Not available
1 1 : ⎭

Stack page selection bit
0 : 0 page
1 : 1 page

Not used (returns "1" when read)
(Do not write "0" to this bit)

Sub-clock (XCIN–XCOUT) oscillating bit
0 : Stopped
1 : Oscillating

Main clock (XIN–XOUT) stop bit
0 : Oscillating
1 : Stopped

Main clock division ratio selection bit
0 : f(XIN)/2 (high-speed mode)
1 : f(XIN)/8 (middle-speed mode)

Internal system clock selection bit
0 : XIN–XOUT selected (middle-/high-speed mode)
1 : XCIN–XCOUT selected (low-speed mode)

Fig. 7 Structure of CPU mode register

MEMORY
Special Function Register (SFR) Area
The Special Function Register area in the zero page contains control registers such as I/O ports and timers.

RAM
RAM is used for data storage and for stack area of subroutine calls and interrupts.

ROM
The first 128 bytes and the last 2 bytes of ROM are reserved for device testing and the rest is user area for storing programs.

Interrupt Vector Area
The interrupt vector area contains reset and interrupt vectors.

Zero Page
Access to this area with only 2 bytes is possible in the zero page addressing mode.

Special Page
Access to this area with only 2 bytes is possible in the special page addressing mode.

RAM area

RAM size (bytes)	Address $XXXX_{16}$
192	$00FF_{16}$
256	$013F_{16}$
384	$01BF_{16}$
512	$023F_{16}$
640	$02BF_{16}$
768	$033F_{16}$
896	$03BF_{16}$
1024	$043F_{16}$
1536	$063F_{16}$
2048	$083F_{16}$

ROM area

ROM size (bytes)	Address $YYYY_{16}$	Address $ZZZZ_{16}$
4096	$F000_{16}$	$F080_{16}$
8192	$E000_{16}$	$E080_{16}$
12288	$D000_{16}$	$D080_{16}$
16384	$C000_{16}$	$C080_{16}$
20480	$B000_{16}$	$B080_{16}$
24576	$A000_{16}$	$A080_{16}$
28672	9000_{16}	9080_{16}
32768	8000_{16}	8080_{16}
36864	7000_{16}	7080_{16}
40960	6000_{16}	6080_{16}
45056	5000_{16}	5080_{16}
49152	4000_{16}	4080_{16}
53248	3000_{16}	3080_{16}
57344	2000_{16}	2080_{16}
61440	1000_{16}	1080_{16}

✻ The start address of the LCD display area can be switched either zero page (addresses 0040_{16}–$012F_{16}$) or 3 page (addresses 0340_{16}–$042F_{16}$) by software. Immediately after reset released, 3 page is selected.

Fig. 8 Memory map diagram

0000_{16}	Port P0 (P0)
0001_{16}	Port P0 direction register (P0D)
0002_{16}	Port P1 (P1)
0003_{16}	Port P1 direction register (P1D)
0004_{16}	Port P2 (P2)
0005_{16}	Port P2 direction register (P2D)
0006_{16}	Port P3 (P3)
0007_{16}	Port P3 direction register (P3D)
0008_{16}	Port P4 (P4)
0009_{16}	Port P4 direction register (P4D)
$000A_{16}$	
$000B_{16}$	
$000C_{16}$	
$000D_{16}$	
$000E_{16}$	
$000F_{16}$	
0010_{16}	
0011_{16}	
0012_{16}	
0013_{16}	
0014_{16}	
0015_{16}	
0016_{16}	PULL register A (PULLA)
0017_{16}	PULL register B (PULLB)
0018_{16}	Transmit/Receive buffer register (TB/RB)
0019_{16}	Serial I/O status register (SIOSTS)
$001A_{16}$	Serial I/O control register (SIOCON)
$001B_{16}$	UART control register (UARTCON)
$001C_{16}$	Baud rate generator (BRG)
$001D_{16}$	
$001E_{16}$	
$001F_{16}$	

0020_{16}	Timer X (low-order) (TXL)
0021_{16}	Timer X (high-order) (TXH)
0022_{16}	Timer Y (low-order) (TYL)
0023_{16}	Timer Y (high-order) (TYH)
0024_{16}	Timer 1 (T1)
0025_{16}	Timer 2 (T2)
0026_{16}	Timer 3 (T3)
0027_{16}	Timer X mode register (TXM)
0028_{16}	Timer Y mode register (TYM)
0029_{16}	Timer 123 mode register (T123M)
$002A_{16}$	
$002B_{16}$	
$002C_{16}$	
$002D_{16}$	
$002E_{16}$	
$002F_{16}$	
0030_{16}	
0031_{16}	A-D control register (ADCON)
0032_{16}	A-D conversion register (low-order) (ADL)
0033_{16}	A-D conversion register (high-order) (ADH)
0034_{16}	
0035_{16}	
0036_{16}	
0037_{16}	LCD control register 1 (LC1)
0038_{16}	LCD control register 2 (LC2)
0039_{16}	LCD mode register (LM)
$003A_{16}$	Interrupt edge selection register (INTEDGE)
$003B_{16}$	CPU mode register (CPUM)
$003C_{16}$	Interrupt request register 1 (IREQ1)
$003D_{16}$	Interrupt request register 2 (IREQ2)
$003E_{16}$	Interrupt control register 1 (ICON1)
$003F_{16}$	Interrupt control register 2 (ICON2)

Fig. 9 Memory map of special function register (SFR)

I/O PORTS
[Direction Registers]

The I/O ports P0–P3 and P4$_1$–P4$_7$ have direction registers which determine the input/output direction of each individual pin. Each bit in a direction register corresponds to one pin, each pin can be set to be input port or output port.

When "0" is written to the bit corresponding to a pin, that pin becomes an input pin. When "1" is written to that bit, that pin becomes an output pin.

If data is read from a pin set to output, the value of the port output latch is read, not the value of the pin itself. Pins set to input are floating. If a pin set to input is written to, only the port output latch is written to and the pin remains floating.

Pull-up Control

By setting the PULL register A (address 0016$_{16}$) or the PULL register B (address 0017$_{16}$), ports P0 to P4 except for port P4$_0$ can control pull-up with a program.

However, the contents of PULL register A and PULL register B do not affect ports programmed as the output ports.
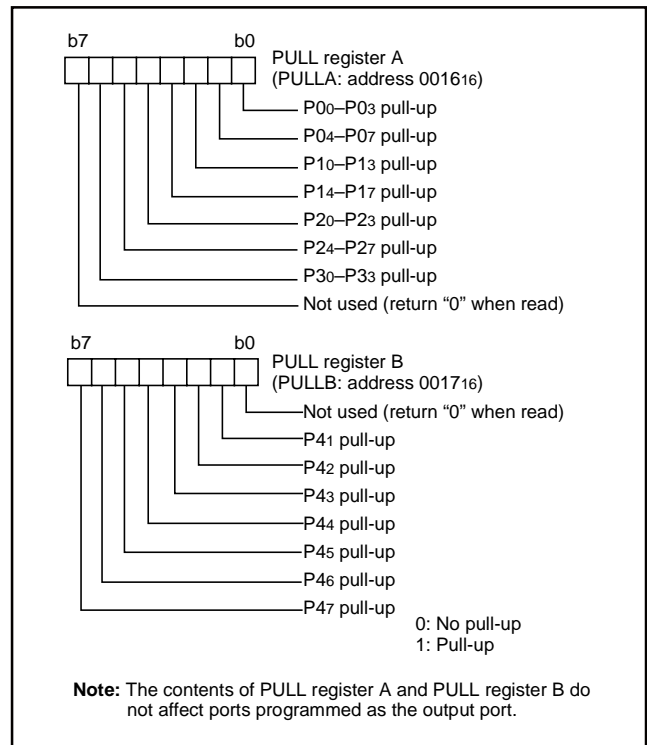
Fig. 10 Structure of PULL register A and PULL register B

Table 5 List of I/O port function

Pin	Name	Input/Output	I/O format	Non-port function	Related SFRs	Ref. No.
P0$_0$–P0$_7$	Port P0	Input/Output, individual bits	CMOS compatible input level CMOS 3-state output		PULL register A	(1)
P1$_0$/A$_{IN4}$– P1$_3$/A$_{IN7}$	Port P1			A-D converter input	PULL register A A-D control register	(2)
P1$_4$–P1$_7$					PULL register A	(1)
P2$_0$–P2$_7$	Port P2	Input/Output, individual bits	CMOS compatible input level CMOS 3-state output	Key input (key-on wake-up) interrupt input	PULL register A Interrupt control register 2	(1)
P3$_0$/A$_{IN0}$– P3$_3$/A$_{IN3}$	Port P3	Input/Output, individual bits	CMOS compatible input level CMOS 3-state output	A-D converter input	PULL register A A-D control register	(2)
P4$_0$/INT$_0$	Port P4	Input	CMOS compatible input level	External interrupt input	PULL register B Interrupt edge select register	(3)
P4$_1$/INT$_1$/ADT		Input/Output, individual bits	CMOS compatible input level CMOS 3-state output			(1)
P4$_2$/CNTR$_0$/ BEEP+				Timer X function I/O	PULL register B Timer X mode register	(4)
P4$_3$/CNTR$_1$/ BEEP-				Timer Y function I/O	PULL register B Timer Y mode register	(5)
P4$_4$/RxD				Serial I/O funtion I/O	PULL register B	(6)
P4$_5$/TxD					Serial I/O control register	(7)
P4$_6$/S$_{CLK}$					Serial I/O status register	(8)
P4$_7$/$\overline{S_{RDY}}$					UART control register	(9)
COM$_0$–COM$_7$, COM$_8$–COM$_{15}$	Common	Output	LCD common output		LCD mode register	
SEG$_0$/COM$_{16}$– SEG$_7$/COM$_{23}$, SEG$_{60}$/COM$_{31}$– SEG$_{67}$/COM$_{24}$	Segment/ Common		LCD segment output LCD common ouput			
SEG$_8$–SEG$_{59}$	Segment		LCD segment output			

(1) Ports P0, P1$_4$–P1$_7$, P2, P4$_1$

Pull-up control

Direction register

Data bus

Port latch

Key-on wake-up interrupt input
INT$_1$ interrupt input, ADT

Except P0, P1$_4$–P1$_7$

(2) Ports P1$_0$–P1$_3$, P3

Pull-up control

Direction register

Data bus

Port latch

A-D converter input

Analog input pin selection bit

(3) Port P4$_0$

Data bus

INT$_0$ interrupt input

(4) Port P4$_2$

Pull-up control

Direction register

Data bus

Port latch

Buzzer output mode
Timer output

CNTR$_0$ interrupt input

(5) Port P4$_3$

Pull-up control

Direction register

Data bus

Port latch

Buzzer output mode
Timer output

CNTR$_1$ interrupt input

Fig. 11 Port block diagram (1)

(6) Port P4₄
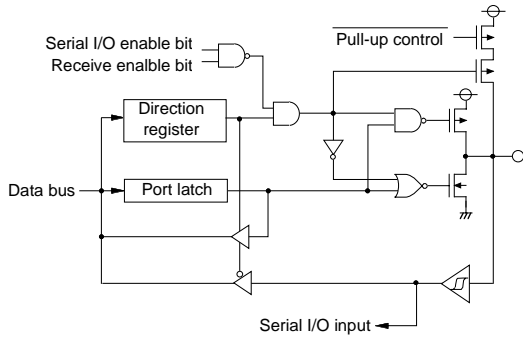
(7) Port P4₅
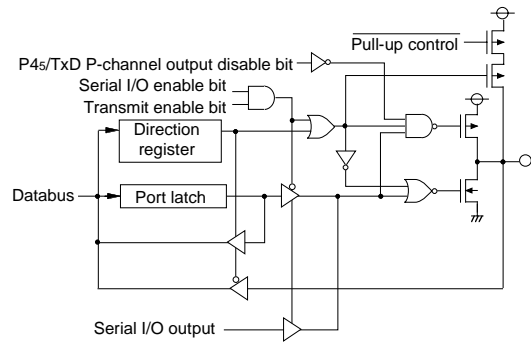
(8) Port P4₆
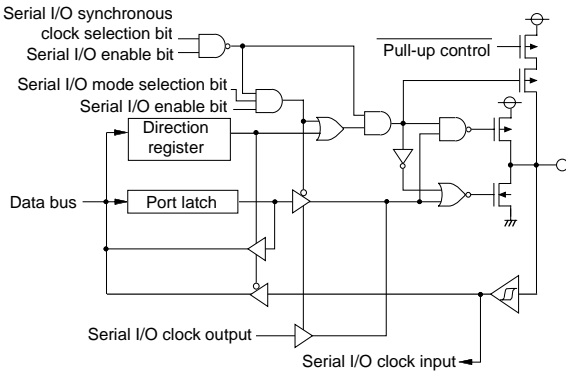
(9) Port P4₇
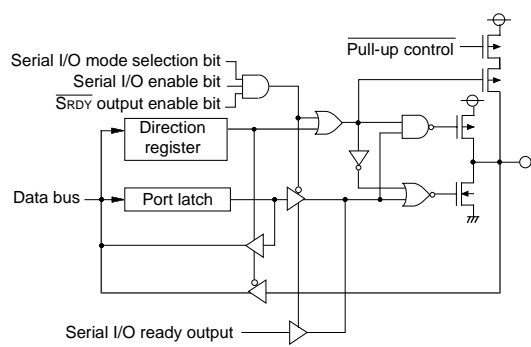
Fig. 12 Port block diagram (2)

RENESAS
Renesas Technology Corp.

INTERRUPTS

Interrupts occur by fourteen sources: five external, eight internal, and one software.

Interrupt Control

Each interrupt except the BRK instruction interrupt have both an interrupt request bit and an interrupt enable bit, and is controlled by the interrupt disable flag. An interrupt occurs if the corresponding interrupt request and enable bits are "1" and the interrupt disable flag is "0".

Interrupt enable bits can be set or cleared by software. Interrupt request bits can be cleared by software, but cannot be set by software. The BRK instruction interrupt and reset cannot be disabled with any flag or bit. The I flag disables all interrupts except the BRK instruction interrupt and reset. If several interrupts requests occurs at the same time the interrupt with highest priority is accepted first.

Interrupt Operation

By acceptance of an interrupt, the following operations are automatically performed:

1. The contents of the program counter and processor status register are automatically pushed onto the stack.
2. The interrupt disable flag is set and the corresponding interrupt request bit is cleared.
3. The interrupt jump destination address is read from the vector table into the program counter.

■Notes on interrupts

When setting the followings, the interrupt request bit may be set to "1".

•When setting external interrupt active edge
  Related register: Interrupt edge selection register (address $3A_{16}$)
  Timer X mode register (address 27_{16})
  Timer Y mode register (address 28_{16})

•When switching interrupt sources of an interrupt vector address where two or more interrupt sources are allocated
  Related register: A-D control regsiter (address 31_{16})

When not requiring for the interrupt occurrence synchronized with these setting, take the following sequence.

①Set the corresponding interrupt enable bit to "0" (disabled).
②Set the interrupt edge select bit (active edge switch bit) or the interrupt source select bit to "1".
③Set the corresponding interrupt request bit to "0" after 1 or more instructions have been executed.
④Set the corresponding interrupt enable bit to "1" (enabled).

Table 6 Interrupt vector addresses and priority

Interrupt Source	Priority	Vector Addresses (Note 1)		Interrupt Request Generating Conditions	Remarks
		High	Low		
Reset **(Note 2)**	1	$FFFD_{16}$	$FFFC_{16}$	At reset	Non-maskable
INT_0	2	$FFFB_{16}$	$FFFA_{16}$	At detection of either rising or falling edge of INT_0 intput	External interrupt (active edge selectable)
INT_1	3	$FFF9_{16}$	$FFF8_{16}$	At detection of either rising or falling edge of INT_1 input	External interrupt (active edge selectable)
Serial I/O reception	4	$FFF7_{16}$	$FFF6_{16}$	At completion of serial I/O data reception	Valid when serial I/O is selected
Serial I/O transmission	5	$FFF5_{16}$	$FFF4_{16}$	At completion of serial I/O transmission shift or when transmission buffer is empty	Valid when serial I/O is selected
Timer X	6	$FFF3_{16}$	$FFF2_{16}$	At timer X underflow	
Timer Y	7	$FFF1_{16}$	$FFF0_{16}$	At timer Y underflow	
Timer 2	8	$FFEF_{16}$	$FFEE_{16}$	At timer 2 underflow	
Timer 3	9	$FFED_{16}$	$FFEC_{16}$	At timer 3 underflow	
$CNTR_0$	10	$FFEB_{16}$	$FFEA_{16}$	At detection of either rising or falling edge of $CNTR_0$ input	External interrupt (active edge selectable)
$CNTR_1$	11	$FFE9_{16}$	$FFE8_{16}$	At detection of either rising or falling edge of $CNTR_1$ input	External interrupt (active edge selectable)
Timer 1	12	$FFE7_{16}$	$FFE6_{16}$	At timer 1 underflow	
Key input (Key-on wake-up)	13	$FFE1_{16}$	$FFE0_{16}$	At falling of port P2 (at input) input logical level AND	External interrupt (falling valid)
A-D conversion	14	$FFDF_{16}$	$FFDE_{16}$	At completion of A-D conversion	Valid when A-D conversion interrupt is selected
BRK instruction	15	$FFDD_{16}$	$FFDC_{16}$	At BRK instruction execution	Non-maskable software interrupt

Notes 1: Vector addresses contain interrupt jump destination addresses.
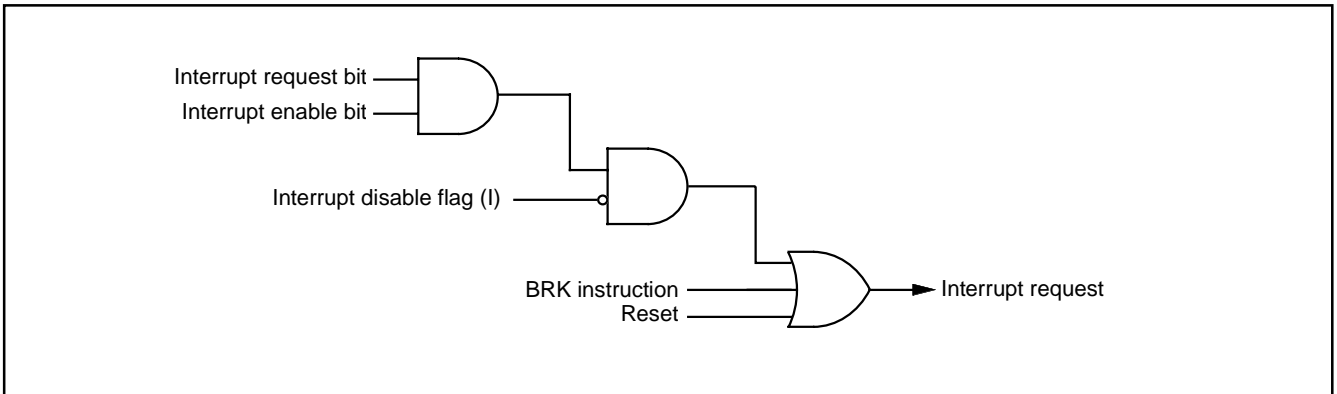**2:** Reset function in the same way as an interrupt with the highest priority.
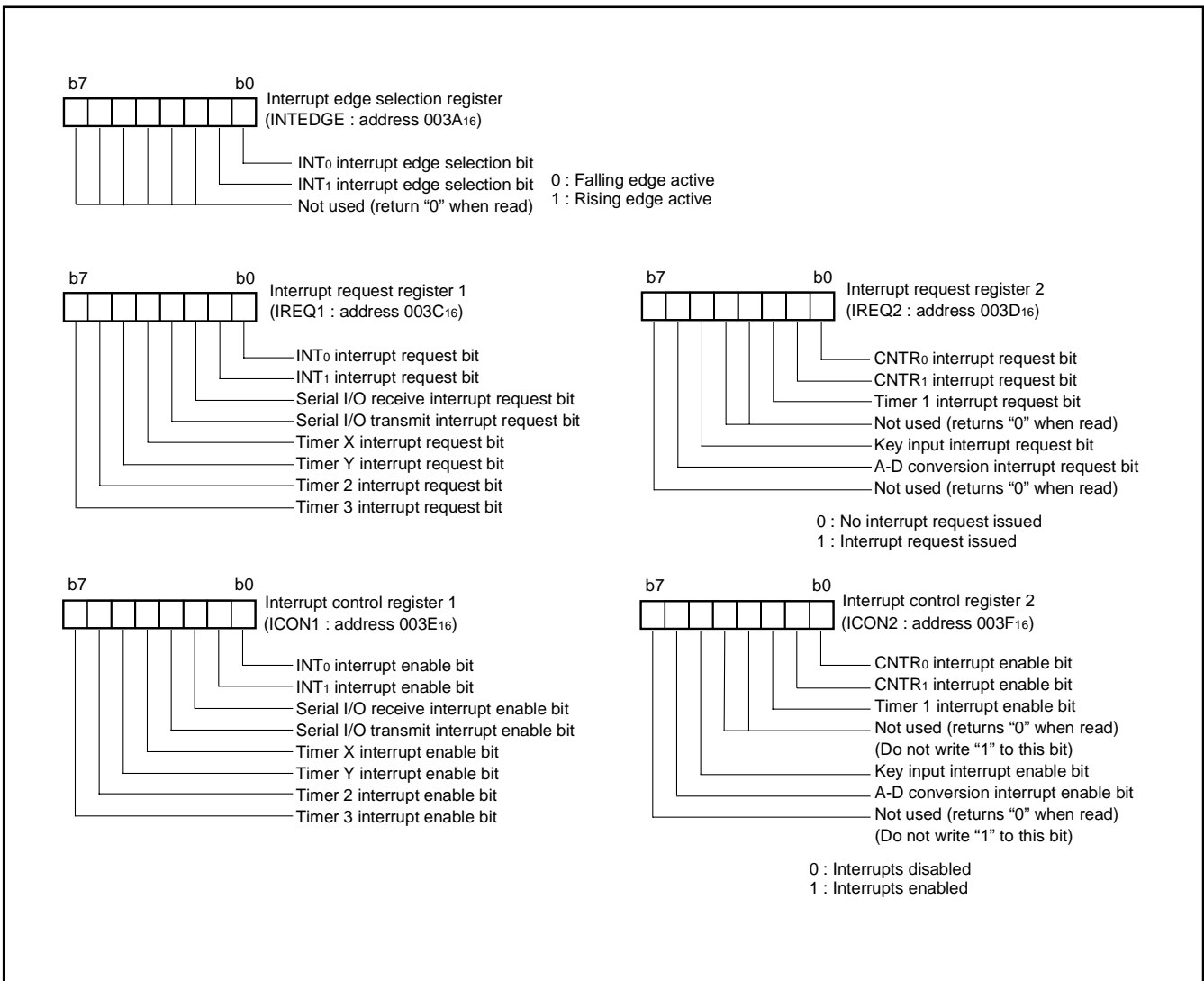
Fig. 13 Interrupt control

Fig. 14 Structure of interrupt-related registers

Key Input Interrupt (Key-on Wake-Up)

A key input interrupt request is generated by applying "L" level to any pin of port P2 that have been set to input mode. In other words, it is generated when AND of input level goes from "1" to "0". An example of using a key input interrupt is shown in Figure 15, where an interrupt request is generated by pressing one of the keys consisted as an active-low key matrix which inputs to ports P2$_0$–P2$_3$.
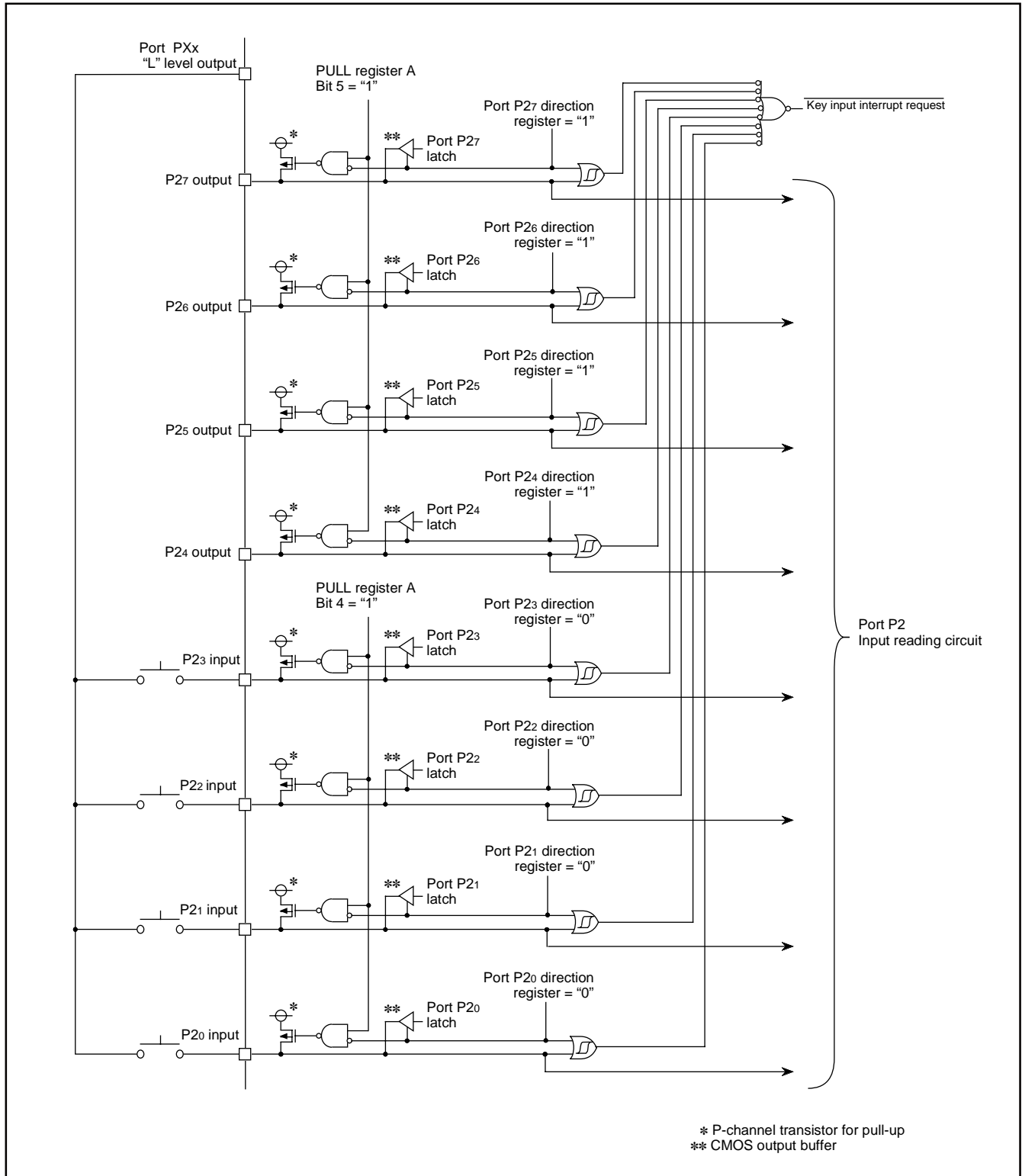
Fig. 15 Connection example when using key input interrupt and port P2 block diagram

TIMERS

The 38C8 group has five timers: timer X, timer Y, timer 1, timer 2, and timer 3. Timer X and timer Y are 16-bit timers, and timer 1, timer 2, and timer 3 are 8-bit timers.

All timers are down count timers. When the timer reaches "00₁₆", an underflow occurs at the next count pulse and the corresponding timer latch is reloaded into the timer and the count is continued. When a timer underflows, the interrupt request bit corresponding to that timer is set to "1".

Read and write operation on 16-bit timer must be performed for both high and low-order bytes. When reading a 16-bit timer, read the high-order byte first. When writing to a 16-bit timer, write the low-order byte first. The 16-bit timer cannot perform the correct operation when reading during the write operation, or when writing during the read operation.
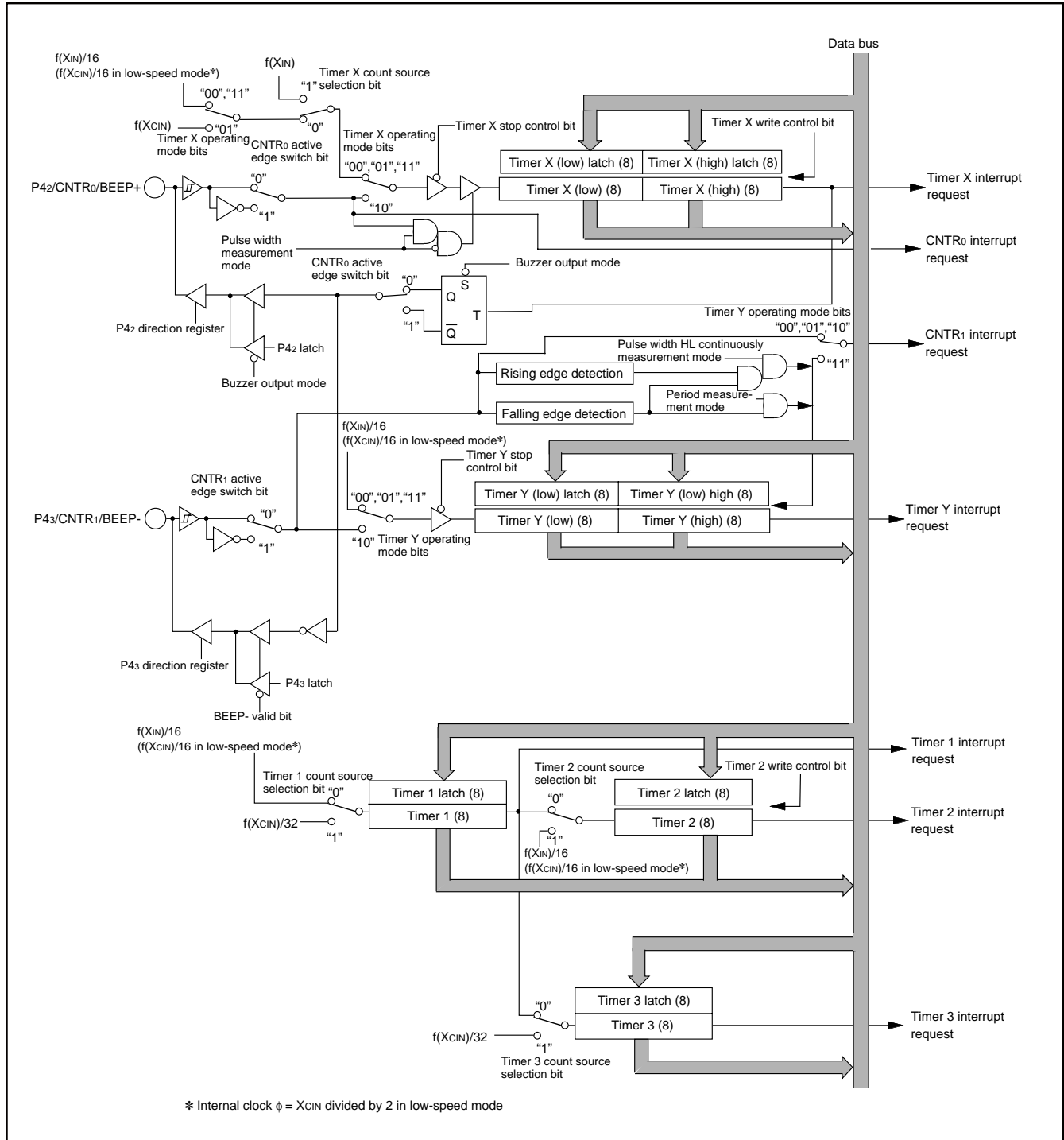
Fig. 16 Timer block diagram

Timer X

Timer X is a 16-bit timer that can be selected in one of four modes and can be controlled the timer X write by setting the timer X mode register.

(1) Timer Mode

When the timer X count source selection bit is "0", the timer counts $f(X_{IN})/16$ (or $f(X_{CIN})/16$ in low-speed mode). When it is "1", the timer counts $f(X_{IN})$.

(2) Buzzer Output Mode

When the timer X count source selection bit is "0", the timer counts $f(X_{CIN})$. When it is "1", the timer counts $f(X_{IN})$.

Each time the timer underflows, a signal output from the BEEP+ pin is inverted. When the BEEP- valid bit is "1", the opposite phase of BEEP+ signal is output from the BEEP- pin. When using the BEEP+ pin and the BEEP- pin, set ports shared with these pins to output.

(3) Event Counter Mode

The timer counts signals input through the CNTR0 pin.

Except for this, the operation in event counter mode is the same as in timer mode. When using a timer in this mode, set the port shared with the CNTR0 pin to input.

(4) Pulse Width Measurement Mode

When the timer X count source selection bit is "0", the count source is $f(X_{IN})/16$ (or $f(X_{CIN})/16$ in low-speed mode). When it is "1", the count source is $f(X_{IN})$.

If CNTR0 active edge switch bit is "0", the timer counts while the input signal of CNTR0 pin is at "H". If it is "1", the timer counts while the input signal of CNTR0 pin is at "L". When using a timer in this mode, set the port shared with the CNTR0 pin to input.

● **Timer X write control**

If the timer X write control bit is "0", when the value is written in the address of timer X, the value is loaded in the timer X and the latch at the same time.

If the timer X write control bit is "1", when the value is written in the address of timer X, the value is loaded only in the latch. The value in the latch is loaded in timer X after timer X underflows.

If the value is written in latch only, unexpected value may be set in the high-order counter when the writing in high-order latch and the underflow of timer X are performed at the same timing.

■ **Notes on CNTR0 interrupt active edge selection**

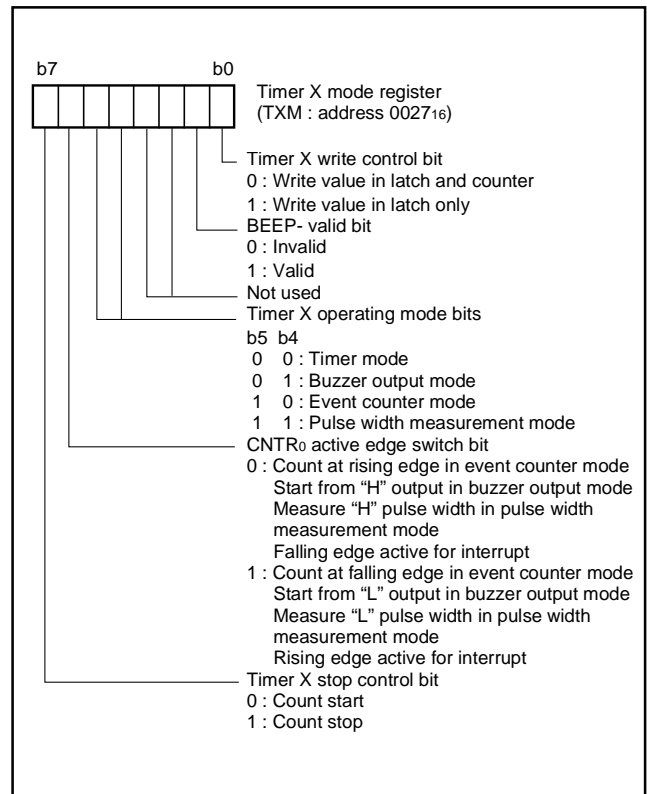CNTR0 interrupt active edge depends on the CNTR0 active edge switch bit.

Fig. 17 Structure of timer X mode register

Timer Y

Timer Y is a 16-bit timer that can be selected in one of four modes.

(1) Timer Mode

The timer counts f(XIN)/16 (or f(XCIN)/16 in low-speed mode).

(2) Period Measurement Mode

CNTR1 interrupt request is generated at rising/falling edge of CNTR1 pin input signal. Simultaneously, the value in timer Y latch is reloaded in timer Y and timer Y continues counting down. Except for the above-mentioned, the operation in period measurement mode is the same as in timer mode.

The timer value just before the reloading at rising/falling of CNTR1 pin input signal is retained until the timer Y is read once after the reload.

The rising/falling timing of CNTR1 pin input signal is found by CNTR1 interrupt. When using a timer in this mode, set the port shared with the CNTR1 pin to input.

(3) Event Counter Mode

The timer counts signals input through the CNTR1 pin.

Except for this, the operation in event counter mode is the same as in timer mode. When using a timer in this mode, set the port shared with the CNTR1 pin to input.

(4) Pulse Width HL Continuously Measurement Mode

CNTR1 interrupt request is generated at both rising and falling edges of CNTR1 pin input signal. Except for this, the operation in pulse width HL continuously measurement mode is the same as in period measurement mode. When using a timer in this mode, set the port shared with the CNTR1 pin to input.

■Notes on CNTR1 interrupt active edge selection

CNTR1 interrupt active edge depends on the CNTR1 active edge switch bit. However, in the pulse width HL continuously measurement mode, CNTR1 interrupt request is generated at both rising and falling edges of CNTR1 pin input signal regardless of the setting of CNTR1 active edge switch bit.
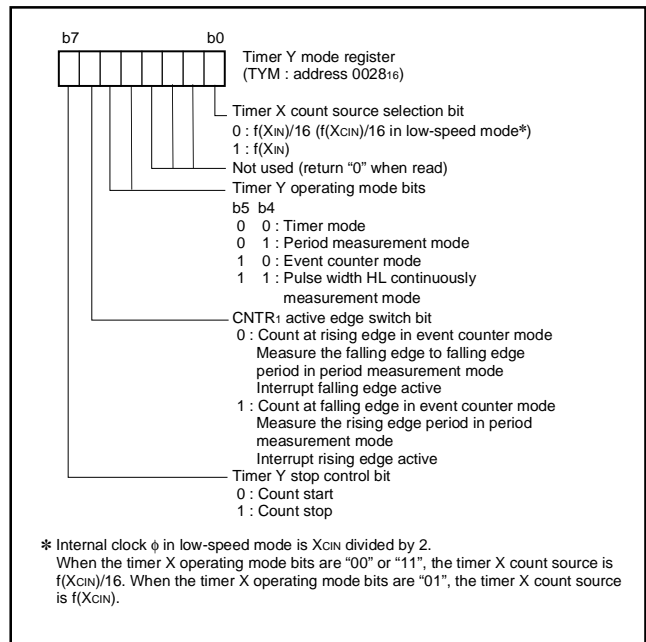

Timer Y mode register
(TYM : address 0028₁₆)

Timer X count source selection bit
0 : f(XIN)/16 (f(XCIN)/16 in low-speed mode*)
1 : f(XIN)
Not used (return "0" when read)
Timer Y operating mode bits
b5 b4
0 0 : Timer mode
0 1 : Period measurement mode
1 0 : Event counter mode
1 1 : Pulse width HL continuously
        measurement mode
CNTR1 active mode switch bit
0 : Count at rising edge in event counter mode
    Measure the falling edge to falling edge
    period in period measurement mode
    Interrupt falling edge active
1 : Count at falling edge in event counter mode
    Measure the rising edge period in period
    measurement mode
    Interrupt rising edge active
Timer Y stop control bit
0 : Count start
1 : Count stop

∗ Internal clock φ in low-speed mode is XCIN divided by 2.
 When the timer X operating mode bits are "00" or "11", the timer X count source is
 f(XCIN)/16. When the timer X operating mode bits are "01", the timer X count source
 is f(XCIN).

Fig. 18 Structure of timer Y mode register

Timer 1, Timer 2, Timer 3

Timer 1, timer 2, and timer 3 are 8-bit timers. The count source for each timer can be selected by the timer 123 mode register. The timer latch value is not affected by a change of the count source. However, because changing the count source may cause an inadvertent count down of the timer. Therefore, rewrite the value of timer whenever the count source is changed.

●Timer 2 write control

If the timer 2 write control bit is "0", when the value is written in the address of timer 2, the value is loaded in the timer 2 and the latch at the same time.

If the timer 2 write control bit is "1", when the value is written in the address of timer 2, the value is loaded only in the latch. The value in the latch is loaded in timer 2 after timer 2 underflows.

■Notes on timer 1 to timer 3

When the count source of timer 1 to 3 is changed, the timer counting value may be changed large because a thin pulse is generated in count input of timer. If timer 1 output is selected as the count source of timer 2 or timer 3, when timer 1 is written, the counting value of timer 2 or timer 3 may be changed large because a thin pulse is generated in timer 1 output.

Therefore, set the value of timer in the order of timer 1, timer 2 and timer 3 after the count source selection of timer 1 to 3.
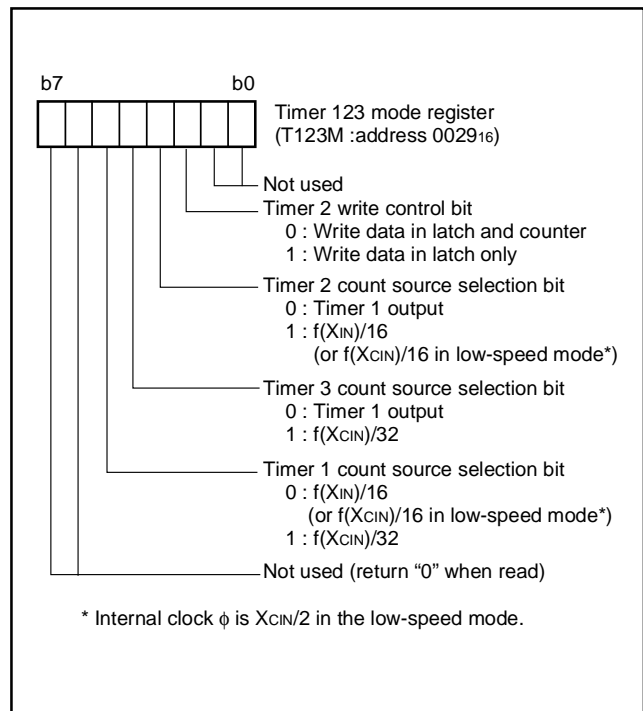
Fig. 19 Structure of timer 123 mode register

SERIAL I/O

Serial I/O can be used as either clock synchronous or asynchronous (UART) serial I/O. A dedicated timer (baud rate generator) is also provided for baud rate generation.

(1) Clock Synchronous Serial I/O Mode

Clock synchronous serial I/O can be selected by setting the mode selection bit of the serial I/O control register to "1".

For clock synchronous serial I/O, the transmitter and the receiver must use the same clock. If an internal clock is used, transfer is started by a write signal to the transmit/receive buffer registers.
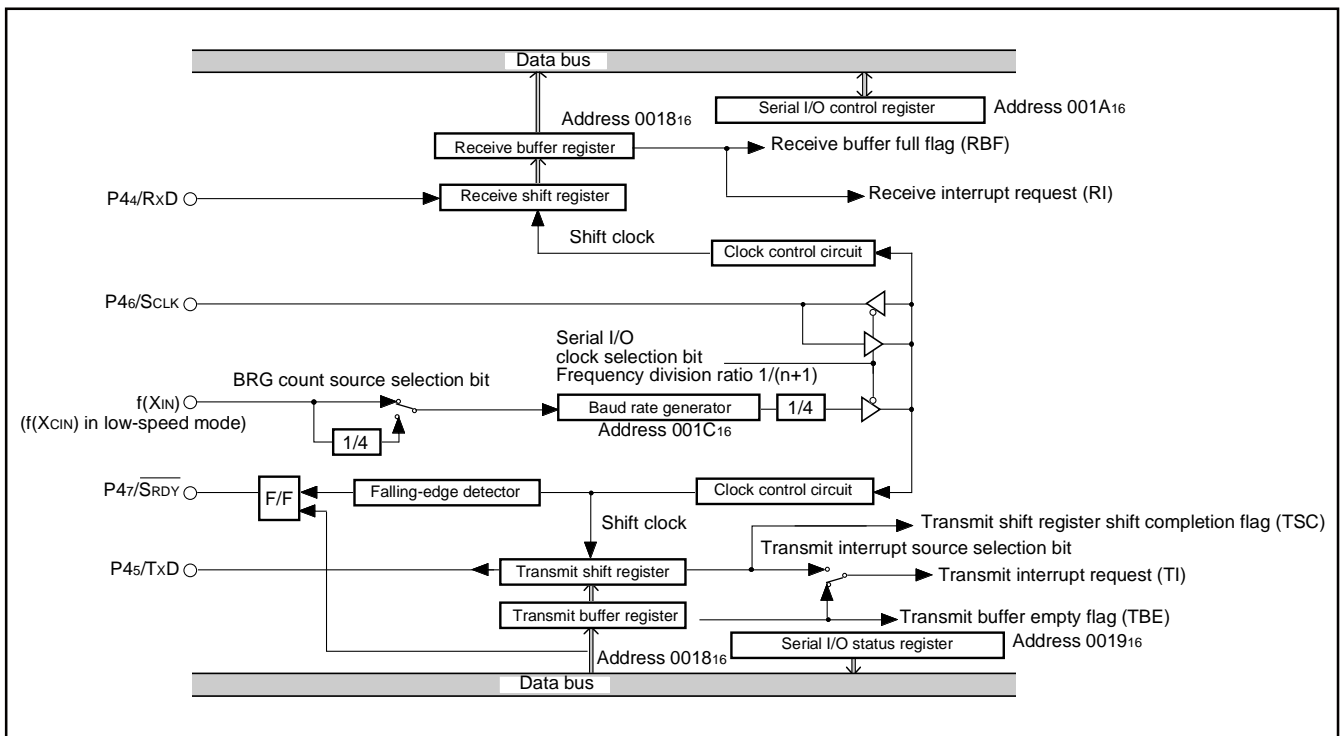
Fig. 20 Block diagram of clock synchronous serial I/O

Notes 1: The transmit interrupt (TI) can be selected to occur either when the transmit buffer register has emptied (TBE=1) or after the transmit shift operation has ended (TSC=1), by setting the transmit interrupt source selection bit (TIC) of the serial I/O control register.
2: If data is written to the transmit buffer register when TSC=0, the transmit clock is generated continuously and serial data is output continuously from the TxD pin.
3: The receive interrupt (RI) is set when the receive buffer full flag (RBF) becomes "1".

Fig. 21 Operation of clock synchronous serial I/O function

(2) Asynchronous Serial I/O (UART) Mode

Clock asynchronous serial I/O mode (UART) can be selected by clearing the serial I/O mode selection bit of the serial I/O control register to "0".

Eight serial data transfer formats can be selected, and the transfer formats used by a transmitter and receiver must be identical.

The transmit and receive shift registers each have a buffer register, but the two buffers have the same address in memory. Since the shift register cannot be written to or read from directly, transmit data is written to the transmit buffer, and receive data is read from the receive buffer.

The transmit buffer can also hold the next data to be transmitted, and the receive buffer register can hold a character while the next character is being received.
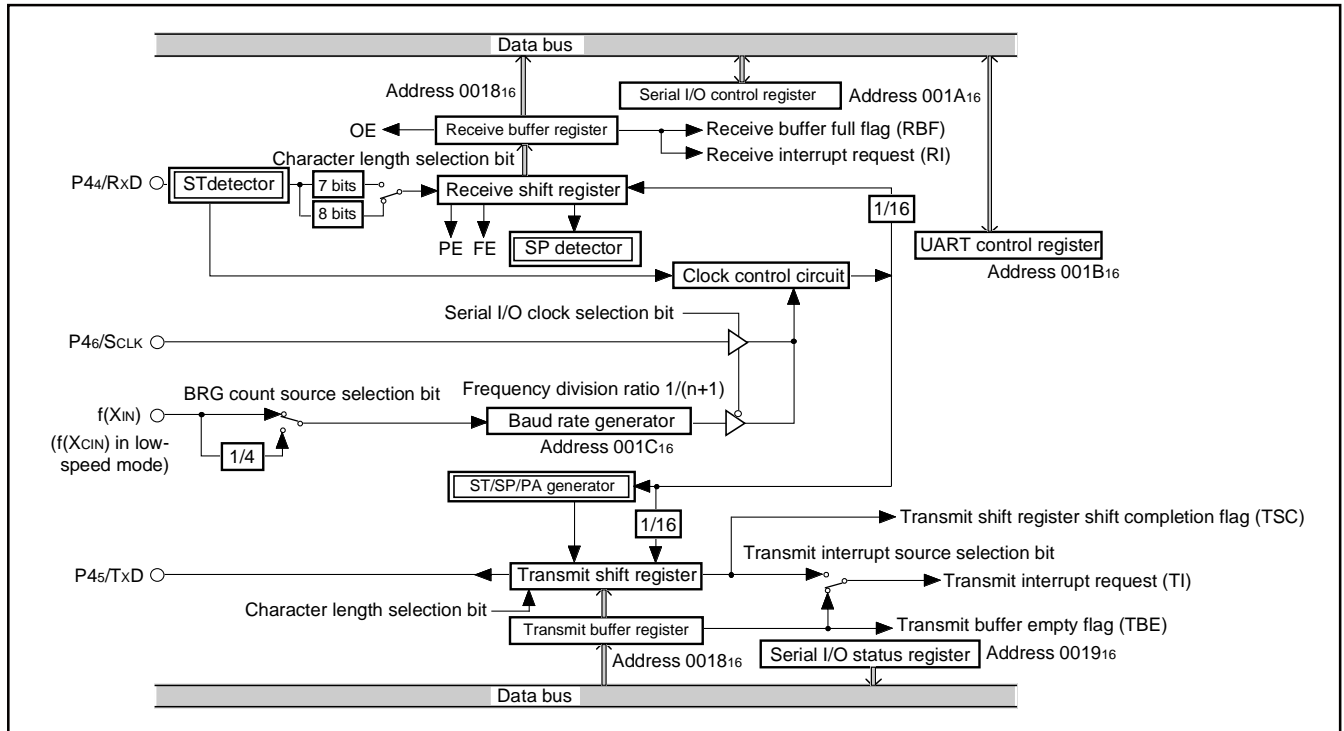
Fig. 22 Block diagram of UART serial I/O

Notes 1: Error flag detection occurs at the same time that the RBF flag becomes "1" (at 1st stop bit, during reception).
   2: The transmit interrupt (TI) can be selected to occur when either the TBE or TSC flag becomes "1" by the setting of the transmit interrupt source selection bit (TIC) of the serial I/O control register.
   3: The receive interrupt (RI) is set when the RBF flag becomes "1".
   4: After data is written to the transmit buffer register when TSC=1, 0.5 to 1.5 cycles of the data shift cycle is necessary until changing to TSC=0.

Fig. 23 Operation of UART serial I/O function

[Transmit Buffer/Receive Buffer Register (TB/RB)] 0018₁₆

The transmit buffer register and the receive buffer register are located at the same address. The transmit buffer register is write-only and the receive buffer register is read-only. If a character bit length is 7 bits, the MSB of data stored in the receive buffer register is "0".

[Serial I/O Status Register (SIOSTS)] 0019₁₆

The read-only serial I/O status register consists of seven flags (bits 0 to 6) which indicate the operating status of the serial I/O function and various errors.

Three of the flags (bits 4 to 6) are valid only in UART mode.

The receive buffer full flag (bit 1) is cleared to "0" when the receive buffer is read.

If there is an error, it is detected at the same time that data is transferred from the receive shift register to the receive buffer register, and the receive buffer full flag is set. A write to the serial I/O status register clears all the error flags OE, PE, FE, and SE. Writing "0" to the serial I/O enable bit (SIOE) also clears all the status flags, including the error flags.

All bits of the serial I/O status register are initialized to "0" at reset, but if the transmit enable bit (bit 4) of the serial I/O control register has been set to "1", the transmit shift register shift completion flag (bit 2) and the transmit buffer empty flag (bit 0) become "1".

[Serial I/O Control Register (SIOCON)] 001A₁₆

The serial I/O control register contains eight control bits for the serial I/O function.

[UART Control Register (UARTCON)] 001B₁₆

This is a 5 bit register containing four control bits, which are valid when UART is selected and set the data format of an data receiver/transfer, and one control bit, which is always valid and sets the output structure of the P4₅/TxD pin.

[Baud Rate Generator (BRG)] 001C₁₆

The baud rate generator determines the baud rate for serial transfer. The baud rate generator divides the frequency of the count source by $1/(n + 1)$, where n is the value written to the baud rate generator.

■Notes on serial I/O

When setting the transmit enable bit to "1", the serial I/O transmit interrupt request bit is automatically set to "1". When not requiring the interrupt occurrence synchronized with the transmission enabled, take the following sequence.

①Set the serial I/O transmit interrupt enable bit to "0" (disabled).

②Set the transmit enable bit to "1".

③Set the serial I/O transmit interrupt request bit to "0" after 1 or more instructions have been executed.

④Set the serial I/O transmit interrupt enable bit to "1" (enabled).

b7   b0   Serial I/O status register
(SIOSTS : address 0019₁₆)

Transmit buffer empty flag (TBE)
0: Buffer full
1: Buffer empty

Receive buffer full flag (RBF)
0: Buffer empty
1: Buffer full

Transmit shift register shift completion flag (TSC)
0: Transmit shift in progress
1: Transmit shift completed

Overrun error flag (OE)
0: No error
1: Overrun error

Parity error flag (PE)
0: No error
1: Parity error

Framing error flag (FE)
0: No error
1: Framing error

Summing error flag (SE)
0: OE U PE U FE =0
1: OE U PE U FE =1

Not used (returns "1" when read)

b7   b0   Serial I/O control register
(SIOCON : address 001A₁₆)

BRG count source selection bit (CSS)
0: f(X$_{IN}$) (f(X$_{CIN}$) in low-speed mode)
1: f(X$_{IN}$)/4 (f(X$_{CIN}$)/4 in low-speed mode)

Serial I/O synchronous clock selection bit (SCS)
0: BRG output divided by 4 when clock synchronous serial
   I/O is selected.
   BRG output divided by 16 when UART is selected.
1: External clock input when clock synchronous serial I/O is
   selected.
   External clock input divided by 16 when UART is selected.

$\overline{SRDY}$ output enable bit (SRDY)
0: P4₇ pin operates as ordinary I/O pin.
1: P4₇ pin operates as $\overline{SRDY}$ output pin.

Transmit interrupt source selection bit (TIC)
0: Interrupt when transmit buffer has emptied
1: Interrupt when transmit shift operation is completed

Transmit enable bit (TE)
0: Transmit disabled
1: Transmit enabled

Receive enable bit (RE)
0: Receive disabled
1: Receive enabled

Serial I/O mode selection bit (SIOM)
0: Asynchronous serial I/O (UART)
1: Clock synchronous serial I/O

Serial I/O enable bit (SIOE)
0: Serial I/O disabled
  (pins P4₄–P4₇ operate as ordinary I/O pins)
1: Serial I/O enabled
  (pins P4₄–P4₇ operate as serial I/O pins)

b7   b0   UART control register
(UARTCON : address 001B₁₆)

Character length selection bit (CHAS)
0: 8 bits
1: 7 bits

Parity enable bit (PARE)
0: Parity checking disabled
1: Parity checking enabled

Parity selection bit (PARS)
0: Even parity
1: Odd parity

Stop bit length selection bit (STPS)
0: 1 stop bit
1: 2 stop bits

P4₅/T$_X$D P-channel output disable bit (POFF)
0: CMOS output (in output mode)
1: N-channel open-drain output (in output mode)

Not used (return "1" when read)

Fig. 24 Structure of serial I/O control registers

A-D CONVERTER
[A-D Conversion Registers (ADL, ADH)] 0032_{16}, 0033_{16}

The A-D conversion registers are read-only registers that contain the result of an A-D conversion. During A-D conversion, do not read these registers.

[A-D Control Register (ADCON)] 0031_{16}

The A-D control register controls the A-D conversion process. Bits 0 to 2 are analog input pin selection bits. Bit 3 is an A-D conversion completion bit and "0" during A-D conversion, then changes to "1" when the A-D conversion is completed. Writing "0" to this bit starts the A-D conversion. When bit 5, which is the A-D external trigger valid bit, is set to "1", A-D conversion is started even by a rising edge or falling edge of an ADT input.

Comparator and Control Circuit

The comparator and control circuit compares an analog input voltage with the comparison voltage and stores the result in the A-D conversion register. When an A-D conversion is completed, the control circuit sets the A-D conversion completion bit and the A-D interrupt request bit to "1".

Because the comparator consists of a capacitor coupling, a deficient conversion speed may cause lack of electric charge and make the conversion accuracy worse. When A-D conversion is performed, set f(X_{IN}) to at least 500 kHz.

When both bit 5 and bit 4 of the CPU mode register are set to "1", A-D conversion is performed by using the built-in self-oscillation circuit.

Trigger Start

When using the A-D external trigger, set the port shared with the ADT pin to input. The polarity of INT1 interrupt edge also applies to the A-D external trigger. When the INT1 interrupt edge polarity is switched after an external trigger is validated, an A-D conversion may be started.

Resistor ladder

The resistor ladder outputs the comparison voltage by dividing the voltage between V_{DD} and V_{SS} by resistance.

Channel Selector

The channel selector selects one of the ports P33/A_{IN3}–P30/A_{IN0} and ports P10/A_{IN4}–P13/A_{IN7}, and inputs it to the comparator.
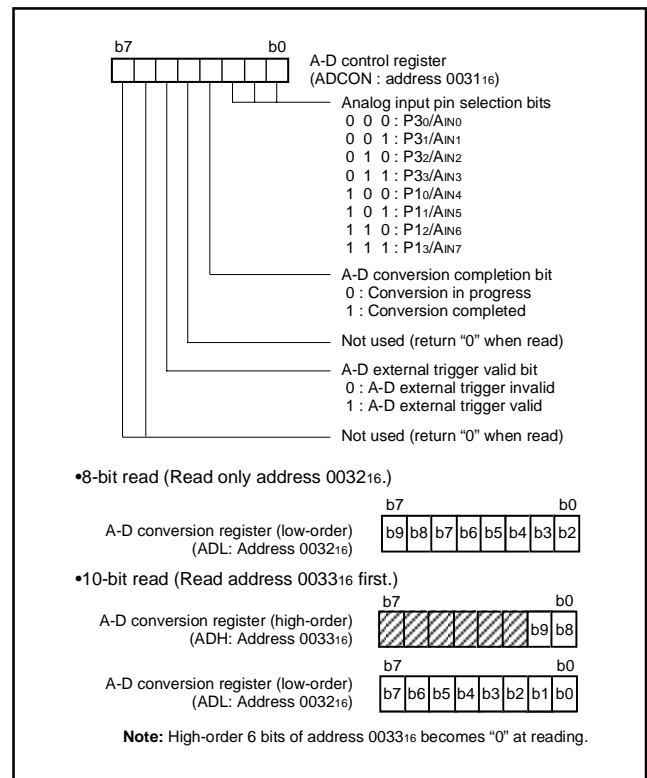
Fig. 25 Structure of A-D control register
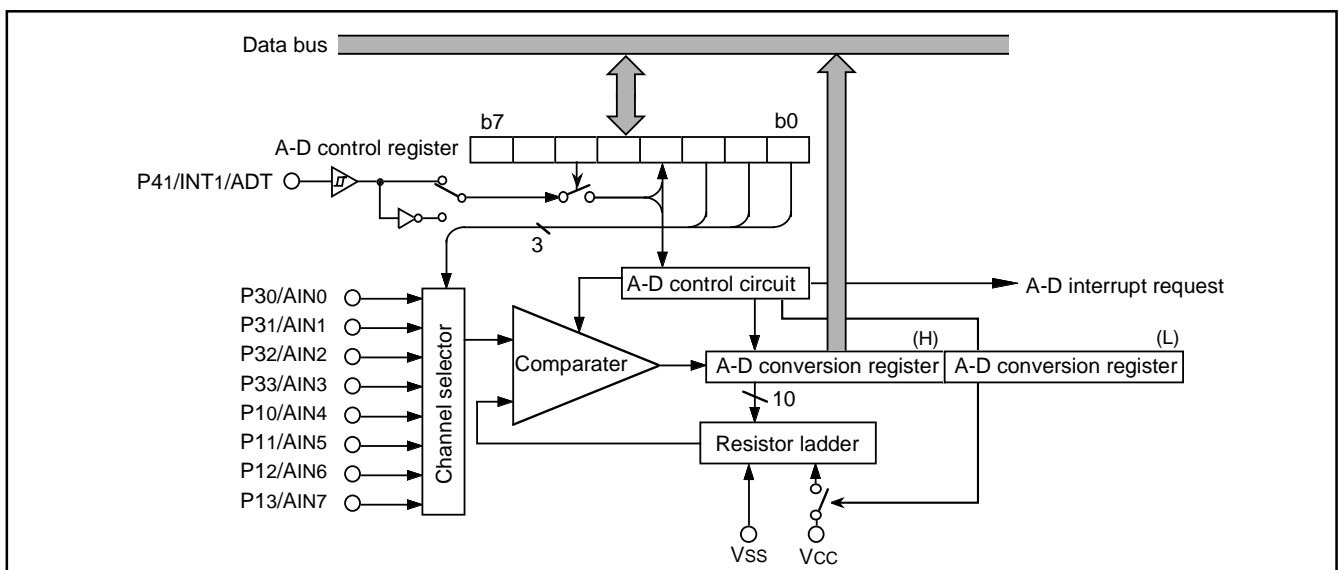
Fig. 26 A-D converter block diagram

LCD CONTROLLER/DRIVER

The 38C8 group has the built-in Liquid Crystal Display (LCD) controller/driver consisting of the following.

- 240-byte LCD display RAM
- 52 or 68 segment driver
- 16 or 32 common driver
- LCD clock generator
- Timing controller

- Bias controller
- Voltage multiplier
- LCD mode register
- LCD control registers 1, 2

A maximum of 68 segment output pins and 32 common output pins can be used for control of external LCD display.
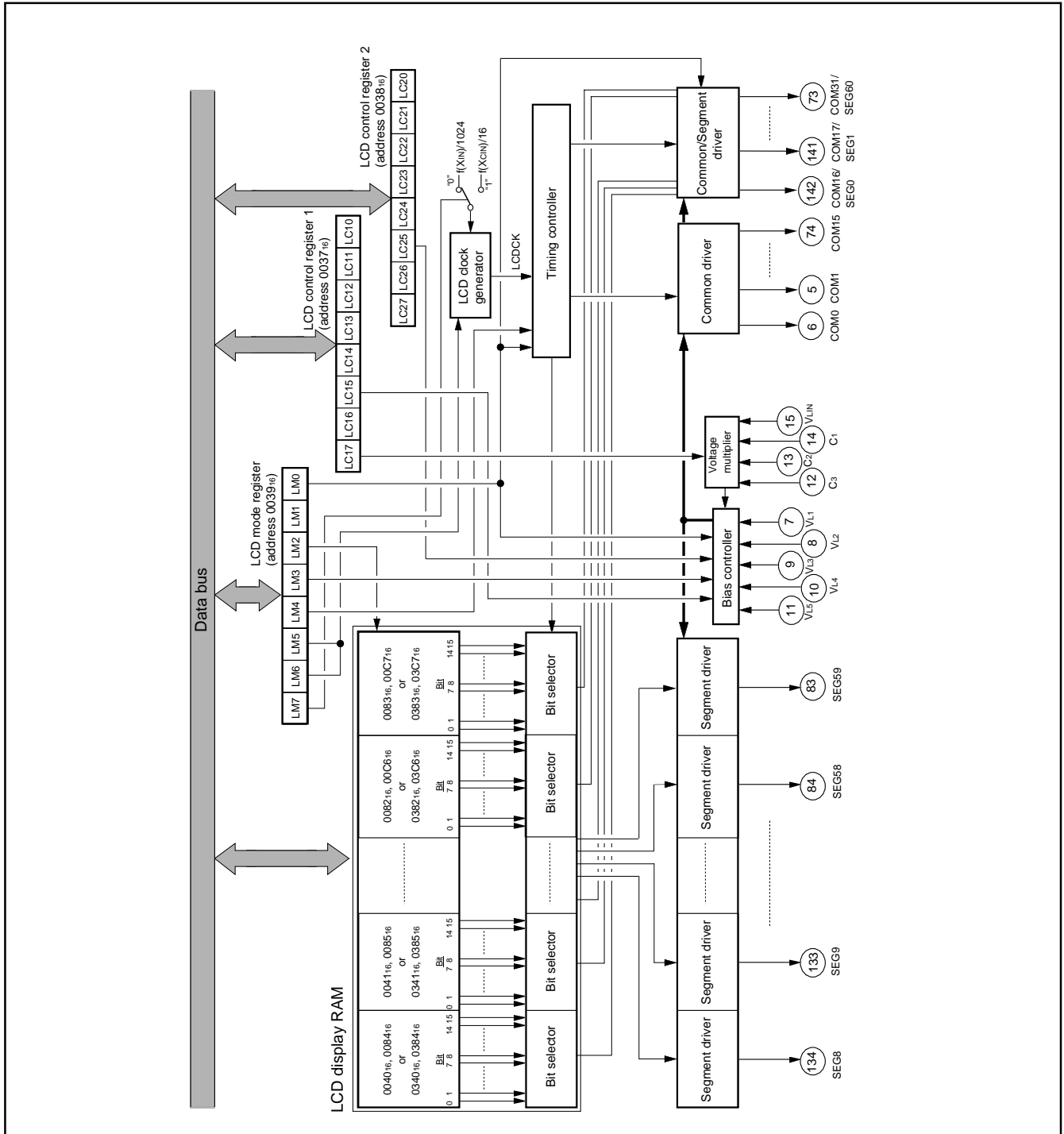
Fig. 27 Block diagram of LCD controller/driver

LCD Controller/Driver Function

The controller/driver performs the bias control and the time sharing control by the LCD control registers 1, 2 (LC1, LC2), and the LCD mode register (LM). The data of corresponding LCDRAM is output from the segment pins according to the output timing of the common pins.

The 38C8 group has the voltage multiplier only for LCD in addition to LCD controller/driver .

[LCD mode register (LM)] 0039_{16}

The LCD mode register is used for setting the LCD controller/driver according to the LCD panel used.

[LCD control register 1 (LC1)] 0037_{16}

The LCD control register 1 controls the voltage multiplier and built-in resistance.

[LCD control register 2 (LC2)] 0038_{16}

The LCD control register 2 is write-only. Setting "1" to bit 5 makes built-in resistance low resistance, and can raise drivability of the segment pins and the common pins.

Table 7 Maximum number of display pixels at each duty ratio

Duty ratio	Maximum number of display pixel
16	16×68 dots (5×7 dots + cursor 2 lines)
32	32×52 dots (5×7 dots + cursor 4 lines)

Note: When executing the STP instruction while operating LCD, execute the STP instruction after prohibiting LCD (set "0" to bit 3 of the LCD mode regsiter).
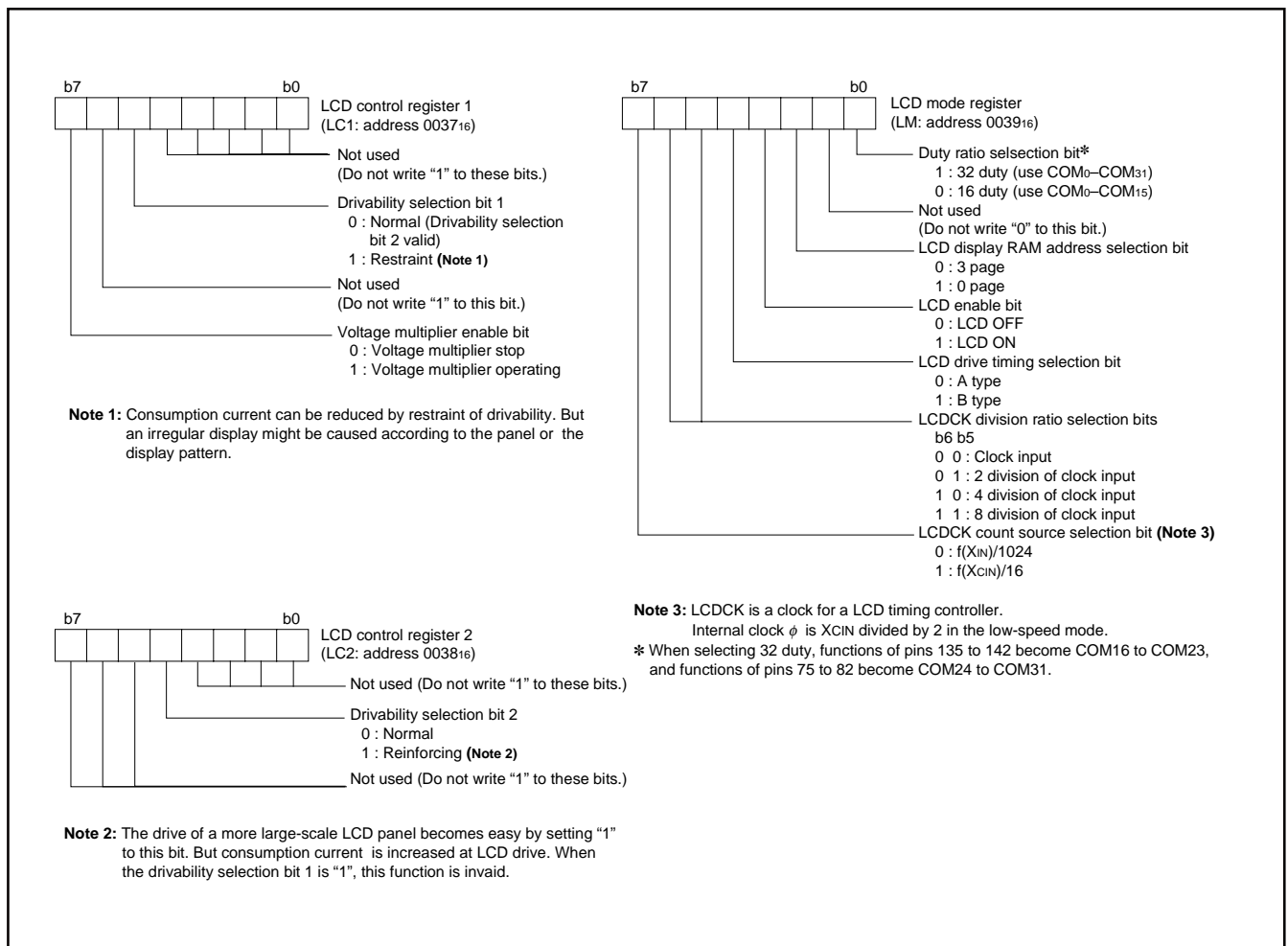
Fig. 28 Structure of LCD control register

Bias Control

In the LCD power source pins (V_{L1}–V_{L5}), 1/7 bias is automatically generated in 32 duty ratio and 1/5 bias is done in 16 duty ratio as well. Be sure to connect the capacitor for smoothness to these pins. When requiring 1/5 bias in 32 duty ratio, use an external resistor to generate a necessary level. In this case the drivability selection bit 1 of LCD control register 1 must be "1".

Voltage Multiplier

When the voltage multiplier is operated after a reference voltage for boosting is applied to LCD power supply V_{LIN}, a voltage that is approximately three times as large as that of V_{LIN} pin occurs at the V_{L5} pin. Operate the voltage multiplier after applying a reference voltage for boosting to V_{LIN}.

The voltage multiplier multiplies a V_{LIN} voltage by charge/discharge of capacitors between C_1 and C_2 pins and to C_3 pin. Accordingly, if a large LCD panel is driven or a vias value is changed owing to an external resistor, a level from V_{L5} pin might be not a requested level. To prevent this, we recommend use of an external power source which can supply stabilized power.

Additionally, when using the voltage multiplier, set a higher resistor value (the sum of R1 to R5) as possible (100 kΩ or more recommended).

Table 8 Bias control and applied voltage to V_{L1}–V_{L5}

Bias value	Voltage value
1/7 bias in 32 duty ratio	$V_{L5} = V_{LCD}$ $V_{L4} = 6/7\ V_{LCD}$ $V_{L3} = 5/7\ V_{LCD}$ $V_{L2} = 2/7\ V_{LCD}$ $V_{L1} = 1/7\ V_{LCD}$
1/5 bias in 16 duty ratio	$V_{L5} = V_{LCD}$ $V_{L4} = 4/5\ V_{LCD}$ $V_{L3} = 3/5\ V_{LCD}$ $V_{L2} = 2/5\ V_{LCD}$ $V_{L1} = 1/5\ V_{LCD}$

Note: V_{LCD} is a value which can be supplied to the LCD panel. Set value which is less than maximum ratings to V_{LCD}.
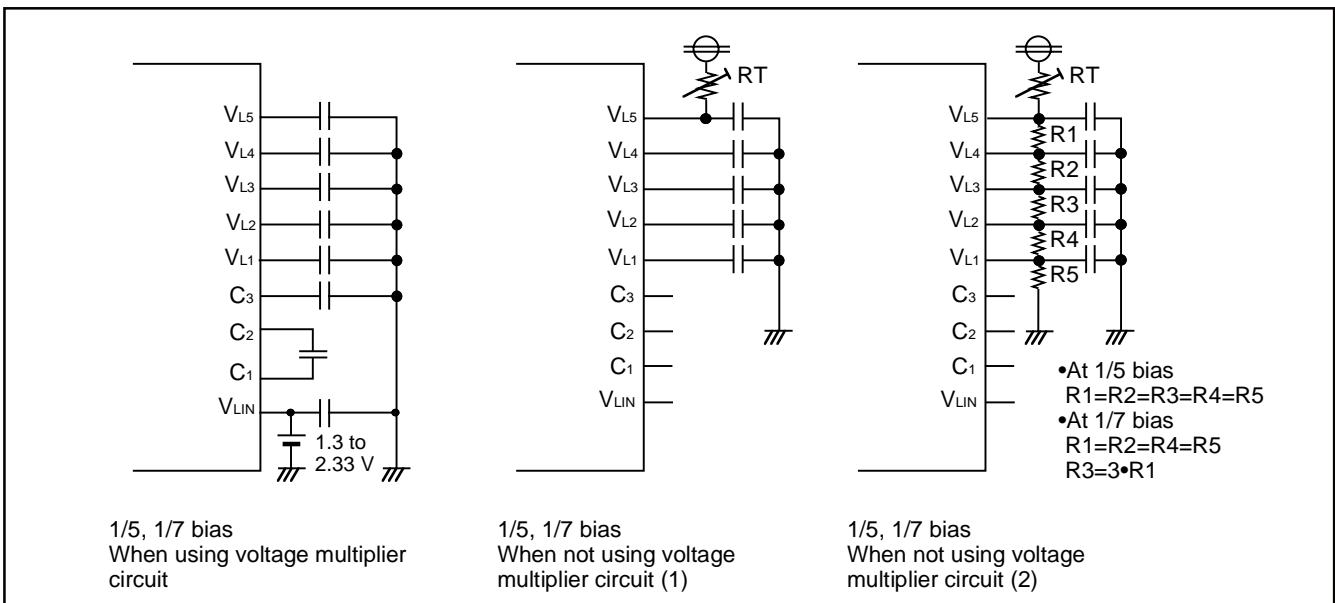
Fig. 29 Example of circuit at each bias

Common Pin and Duty Ratio Control

The common pins (COM0–COM31) to be used are determined by duty ratio.

Select duty ratio by the duty ratio selection bit (bit 0 of the LCD mode register).

Table 9 Duty ratio control and common pins used

Duty ratio	Duty ratio selection bit	Common pins used
16	0	COM0–COM15 **(Note)**
32	1	COM0–COM31

Note: The SEG0/COM16–SEG7/COM23 pins are used as the SEG0–SEG7.
The SEG67/COM24–SEG60/COM31 pins are used as the SEG67–SEG60.

LCD Display RAM

When LCD display RAM address selection bit is "0", the area of addresses 0340₁₆ to 042F₁₆ is the designated RAM for the LCD display. When the bit is "1", the area of addresses 0040₁₆ to 012F₁₆ is the designated RAM for it. When "1"s are written to these addresses, the corresponding segments of the LCD display panel are turned on.

LCD Drive Timing

The LCDCK timing frequency (LCD drive timing) is generated internally and the frame frequency can be determined with the following equation;

$$f(LCDCK) = \frac{(\text{frequency of count source for LCDCK})}{(\text{divider division ratio for LCD})}$$

$$\text{Frame frequency} = \frac{f(LCDCK)}{(\text{duty ratio})}$$
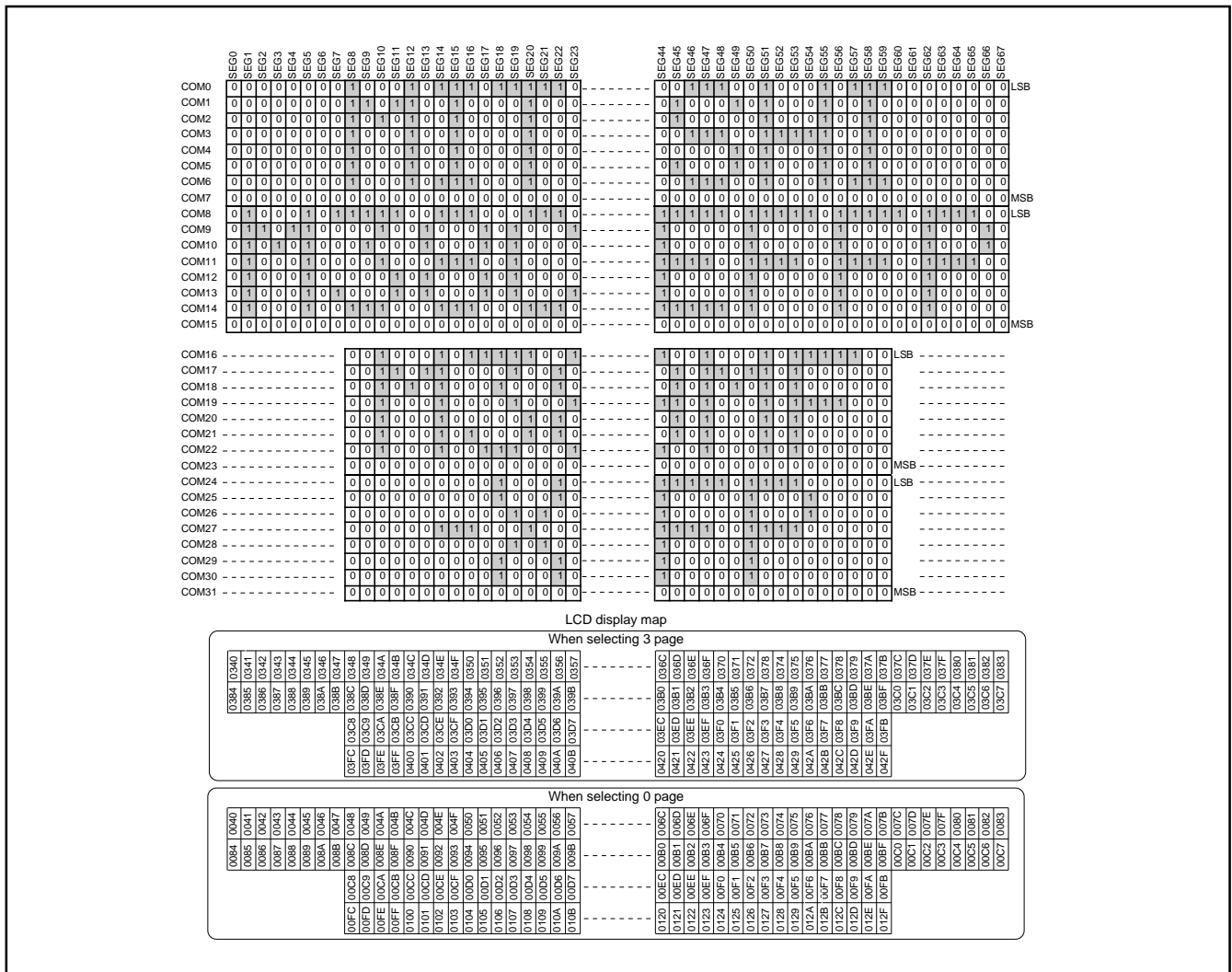
Fig. 30 LCD display RAM map

RENESAS
Renesas Technology Corp.
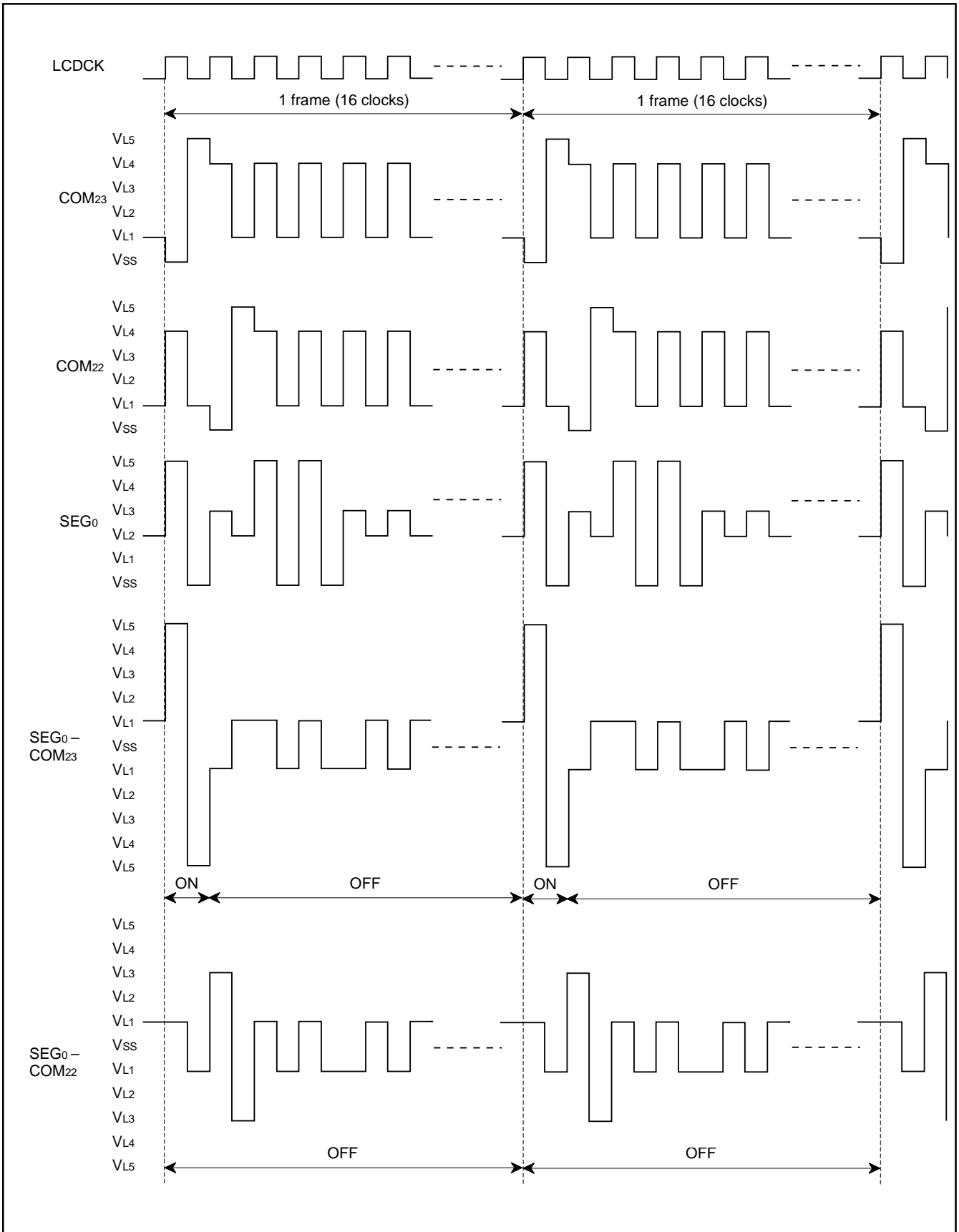
Fig. 31 LCD drive waveform (16 duty ratio, 1/5 bias, A type)
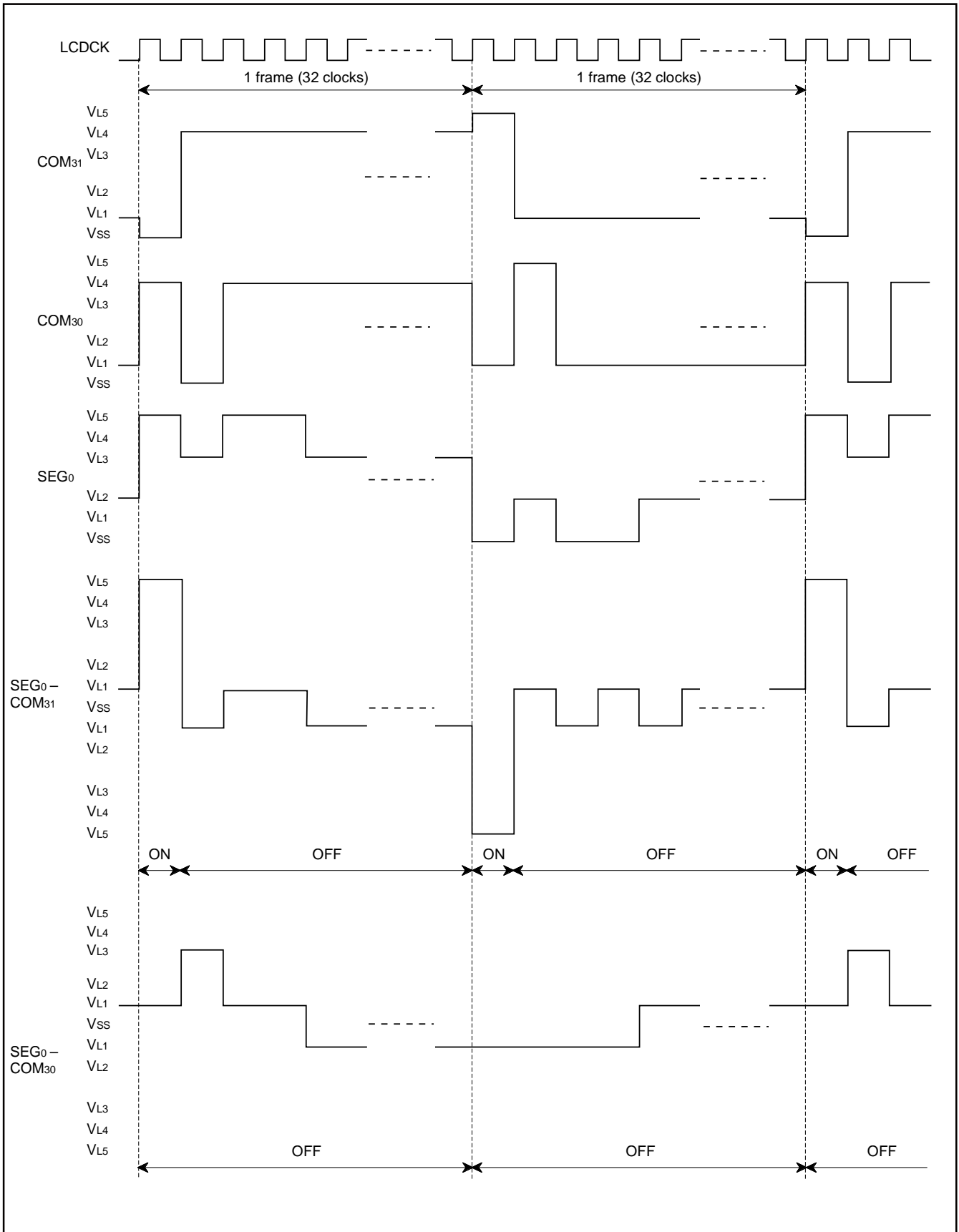
Fig. 32 LCD drive waveform (32 duty ratio, 1/7 bias, B type)

RESET CIRCUIT

To reset the microcomputer, $\overline{\text{RESET}}$ pin should be held at an "L" level for 2 μs or more. Then the $\overline{\text{RESET}}$ pin is returned to an "H" level (the power source voltage should be between V_{CC} (min.) and 5.5 V, and the quartz-crystal oscillator should be stable), reset is released. After the reset is completed, the program starts from the address contained in address FFFD$_{16}$ (high-order byte) and address FFFC$_{16}$ (low-order byte). Make sure that the reset input voltage is less than 0.2V_{CC} when a power source voltage passes V_{CC} (min.).
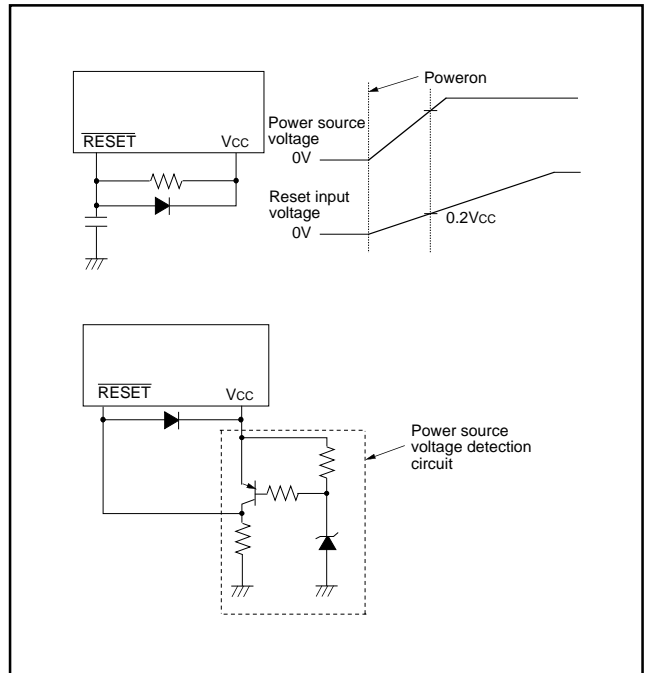
Fig. 33 Reset circuit example

Fig. 34 Reset sequence
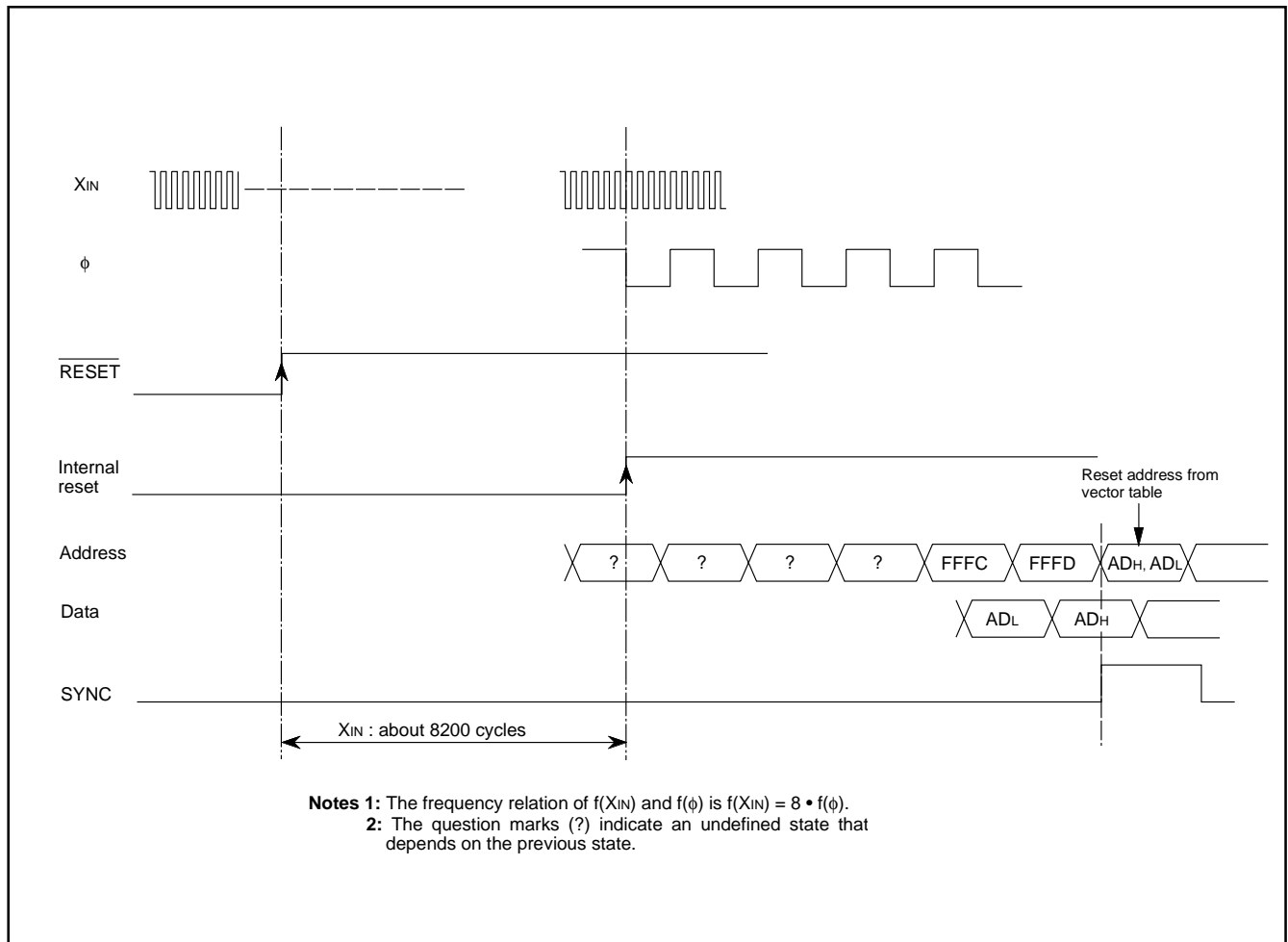
Notes 1: The frequency relation of f(X$_{IN}$) and f(ϕ) is f(X$_{IN}$) = 8 • f(ϕ).
2: The question marks (?) indicate an undefined state that depends on the previous state.

		Address	Register contents			Address	Register contents
(1)	Port P0 direction register	0001_{16}	00_{16}	(21)	A-D control register	0031_{16}	08_{16}
(2)	Port P1 direction register	0003_{16}	00_{16}	(22)	A-D conversion register (low-order)	0032_{16}	XX_{16}
(3)	Port P2 direction register	0005_{16}	00_{16}	(23)	A-D conversion register (high-order)	0033_{16}	XX_{16}
(4)	Port P3 direction register	0007_{16}	00_{16}	(24)	LCD control register 1	0037_{16}	00_{16}
(5)	Port P4 direction register	0009_{16}	00_{16}	(25)	LCD control register 2	0038_{16}	00_{16}
(6)	PULL register A	0016_{16}	00_{16}	(26)	LCD mode register	0039_{16}	03_{16}
(7)	PULL register B	0017_{16}	00_{16}	(27)	Interrupt edge selection register	$003A_{16}$	00_{16}
(8)	Serial I/O status register	0019_{16}	80_{16}	(28)	CPU mode register	$003B_{16}$	$4C_{16}$
(9)	Serial I/O control register	$001A_{16}$	00_{16}	(29)	Interrupt request register 1	$003C_{16}$	00_{16}
(10)	UART control register	$001B_{16}$	$E0_{16}$	(30)	Interrupt request register 2	$003D_{16}$	00_{16}
(11)	Timer X (low-order)	0020_{16}	FF_{16}	(31)	Interrupt control register 1	$003E_{16}$	00_{16}
(12)	Timer X (high-order)	0021_{16}	FF_{16}	(32)	Interrupt control register 2	$003F_{16}$	00_{16}
(13)	Timer Y (low-order)	0022_{16}	FF_{16}	(33)	Processor status register	(PS)	$\boxed{x\,x\,x\,x\,x\,1\,x\,x}$
(14)	Timer Y (high-order)	0023_{16}	FF_{16}	(34)	Program counter	(PCH)	Contents of address FFFD16
(15)	Timer 1	0024_{16}	FF_{16}			(PCL)	Contents of address FFFC16
(16)	Timer 2	0025_{16}	01_{16}				
(17)	Timer 3	0026_{16}	FF_{16}				
(18)	Timer X mode register	0027_{16}	00_{16}				
(19)	Timer Y mode register	0028_{16}	00_{16}				
(20)	Timer 123 mode register	0029_{16}	00_{16}				

Note: The contents of all other register and RAM are undefined after reset, so they must be initialized by software.
X : Undefined

Fig. 35 Internal status at reset

CLOCK GENERATING CIRCUIT

The 38C8 group has two built-in oscillation circuits: main clock XIN-XOUT oscillation circuit and sub-clock XCIN-XCOUT oscillation circuit. An oscillation circuit can be formed by connecting a resonator between XIN and XOUT (XCIN and XCOUT). RC oscillation is available for XIN-XOUT.

Immediately after reset is released, the XIN-XOUT oscillation circuit starts oscillating, and XCIN and XCOUT pins go to high impedance state.

Main Clock

An oscillation circuit by a resonator can be formed by setting the OSCSEL pin is set to "L" level and connecting a resonator between XIN and XOUT. Use the circuit constants in accordance with the resonator manufacturer's recommended values. No external resistor is needed between XIN and XOUT since a feed-back resistor exists on-chip. To supply a clock signal externally, make the XOUT pin open in the "L" level state of the OSCSEL pin, and supply the clock from the XIN pin. The RC oscillation circuit can be formed by setting the OSCSEL pin to "H" level and connecting a resistor between the XIN pin and the XOUT pin. At this time, the feed-back resistor is cut off. The frequency of the RC oscillation changes owing to a parasitic capacitance or the wiring length etc. of the printed circuit board. Do not use the RC oscillation in the usage which the frequency accuracy of the main clock is needed.

Sub-clock

Connect a resonator between XCIN and XCOUT. An external feed-back resistor is needed between XCIN and XCOUT since a feed-back resistor does not exist on-chip. The sub-clock XCIN-XCOUT oscillation circuit cannot directly input clocks that are externally generated. Accordingly, be sure to cause an external resonator to oscillate.

Frequency Control
(1) Middle-speed Mode

The internal clock ϕ is the frequency of XIN divided by 8. After reset is released, this mode is selected.

(2) High-speed Mode

The internal clock ϕ is the frequency of XIN divided by 2.

(3) Low-speed Mode

The internal clock ϕ is the frequency of XCIN divided by 2.
A low-power consumption operation can be realized by stopping the main clock XIN in this mode. To stop the main clock, set bit 5 of the CPU mode register to "1". When the main clock XIN is restarted, set enough time for oscillation to stabilize by programming.

■Notes on clock generating circuit

If you switch the mode between middle/high-speed and low-speed, stabilize both XIN and XCIN oscillations. The sufficient time is required for the sub-clock to stabilize, especially immediately after power on and at returning from stop mode. When switching the mode between middle/high-speed and low-speed, set the frequency on condition that f(XIN) > 3•f(XCIN).

Oscillation Control
(1) Stop Mode

If the STP instruction is executed, the internal clock ϕ stops at an "H" level, and XIN and XCIN oscillators stop. Timer 1 is set to "FF16" and timer 2 is set to "0116."

Either XIN divided by 16 or XCIN divided by 16 is input to timer 1 as count source, and the output of timer 1 is connected to timer 2. The bits except bit 4 of the timer 123 mode register are cleared to "0." Set the interrupt enable bits of timer 1 and timer 2 to disabled ("0") before executing the STP instruction.

Oscillator restarts at reset or when an external interrupt is received, but the internal clock ϕ is not supplied to the CPU until timer 2 underflows. This allows time for the clock circuit oscillation to stabilize.

(2) Wait Mode

If the WIT instruction is executed, the internal clock ϕ stops at an "H" level. The states of XIN and XCIN are the same as the state before executing the WIT instruction. The internal clock ϕ restarts at reset or when an interrupt is received. Since the oscillator does not stop, normal operation can be started immediately after the clock is restarted.
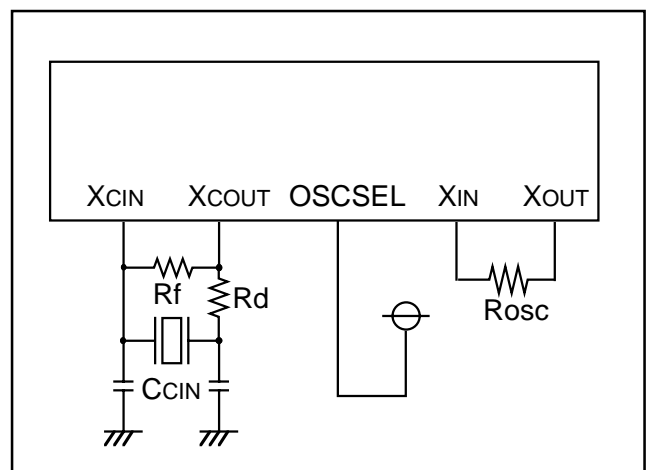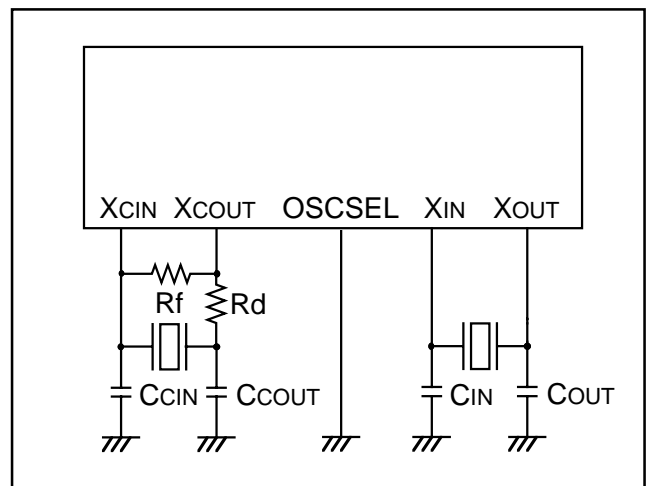

Fig. 36 RC oscillation circuit
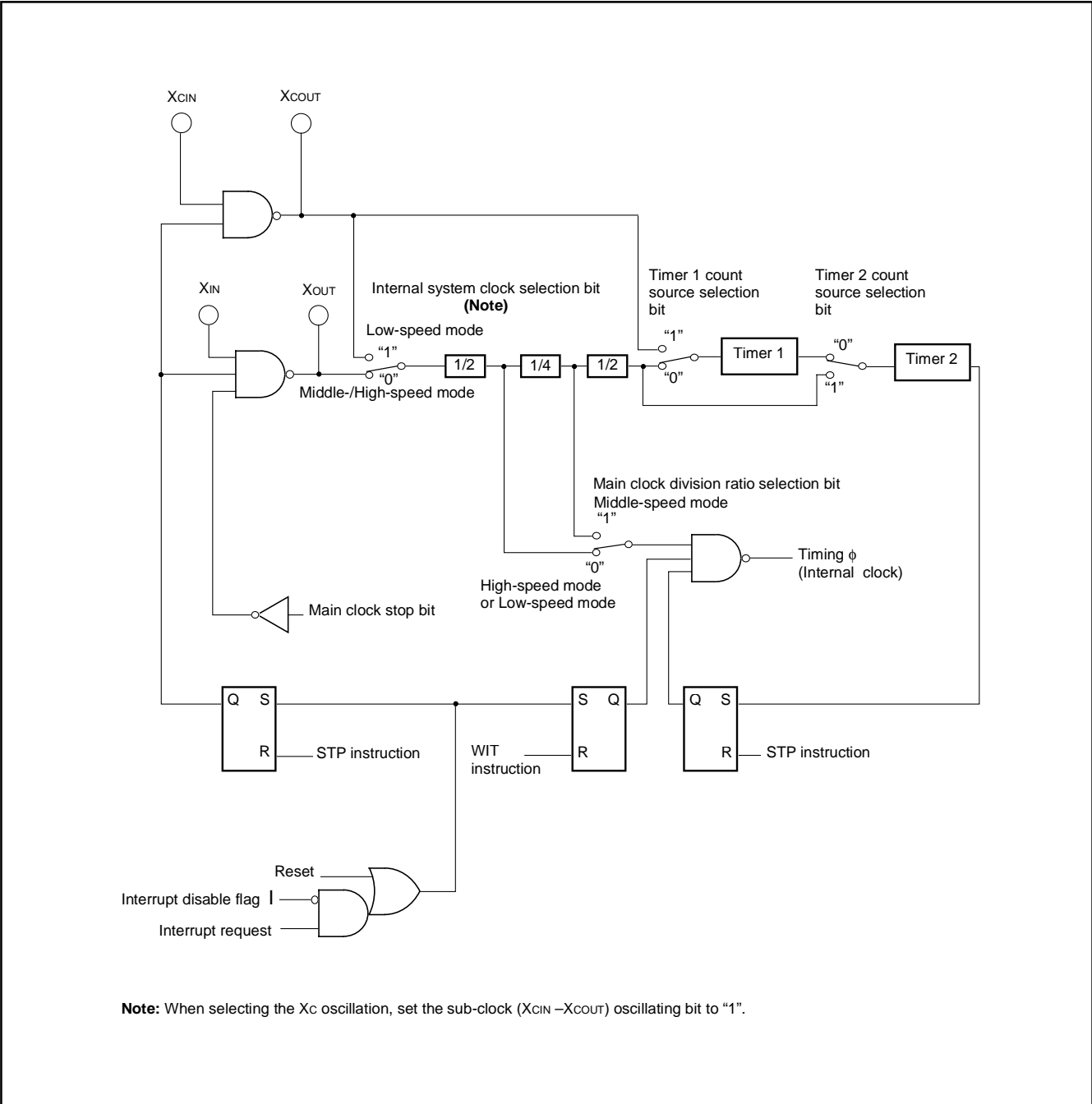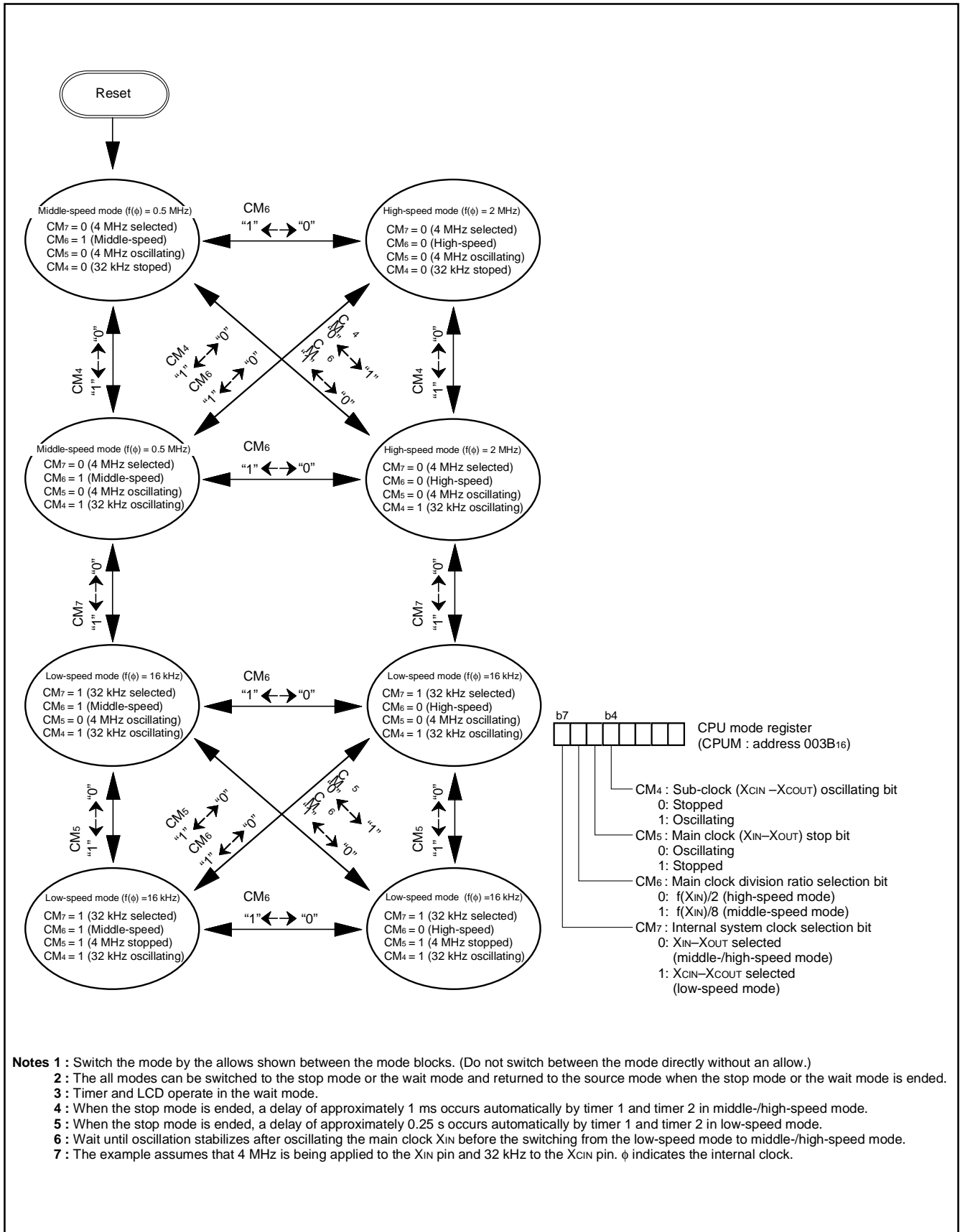

Fig. 37 Resonator circuit

Fig. 38 Clock generating circuit block diagram

Reset

Middle-speed mode (f(φ) = 0.5 MHz)
CM7 = 0 (4 MHz selected)
CM6 = 1 (Middle-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 0 (32 kHz stoped)

CM6 "1" ←→ "0"

High-speed mode (f(φ) = 2 MHz)
CM7 = 0 (4 MHz selected)
CM6 = 0 (High-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 0 (32 kHz stoped)

CM4 "0" / "1"

CM4 "1" / "0"
CM6 "1" / "0"

CM5 4 / CM6 "1"

CM4 "0"

Middle-speed mode (f(φ) = 0.5 MHz)
CM7 = 0 (4 MHz selected)
CM6 = 1 (Middle-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 1 (32 kHz oscillating)

CM6 "1" ←→ "0"

High-speed mode (f(φ) = 2 MHz)
CM7 = 0 (4 MHz selected)
CM6 = 0 (High-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 1 (32 kHz oscillating)

CM7 "1" / "0"

CM7 "1" / "0"

Low-speed mode (f(φ) =16 kHz)
CM7 = 1 (32 kHz selected)
CM6 = 1 (Middle-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 1 (32 kHz oscillating)

CM6 "1" ←→ "0"

Low-speed mode (f(φ) =16 kHz)
CM7 = 1 (32 kHz selected)
CM6 = 0 (High-speed)
CM5 = 0 (4 MHz oscillating)
CM4 = 1 (32 kHz oscillating)

CM5 "0" / "1"

CM5 "1" / "0"
CM6 "1" / "0"

CM5 5 / CM6 "1"

CM5 "1" / "0"

Low-speed mode (f(φ) =16 kHz)
CM7 = 1 (32 kHz selected)
CM6 = 1 (Middle-speed)
CM5 = 1 (4 MHz stopped)
CM4 = 1 (32 kHz oscillating)

CM6 "1" ←→ "0"

Low-speed mode (f(φ) =16 kHz)
CM7 = 1 (32 kHz selected)
CM6 = 0 (High-speed)
CM5 = 1 (4 MHz stopped)
CM4 = 1 (32 kHz oscillating)

b7   b4

CPU mode register
(CPUM : address 003B16)

CM4 : Sub-clock (XCIN –XCOUT) oscillating bit
0: Stopped
1: Oscillating
CM5 : Main clock (XIN–XOUT) stop bit
0: Oscillating
1: Stopped
CM6 : Main clock division ratio selection bit
0: f(XIN)/2 (high-speed mode)
1: f(XIN)/8 (middle-speed mode)
CM7 : Internal system clock selection bit
0: XIN–XOUT selected
(middle-/high-speed mode)
1: XCIN–XCOUT selected
(low-speed mode)

Notes 1 : Switch the mode by the allows shown between the mode blocks. (Do not switch between the mode directly without an allow.)
    2 : The all modes can be switched to the stop mode or the wait mode and returned to the source mode when the stop mode or the wait mode is ended.
    3 : Timer and LCD operate in the wait mode.
    4 : When the stop mode is ended, a delay of approximately 1 ms occurs automatically by timer 1 and timer 2 in middle-/high-speed mode.
    5 : When the stop mode is ended, a delay of approximately 0.25 s occurs automatically by timer 1 and timer 2 in low-speed mode.
    6 : Wait until oscillation stabilizes after oscillating the main clock XIN before the switching from the low-speed mode to middle-/high-speed mode.
    7 : The example assumes that 4 MHz is being applied to the XIN pin and 32 kHz to the XCIN pin. φ indicates the internal clock.

Fig. 39 State transitions of system clock

NOTES ON PROGRAMMING
Processor Status Register

The contents of the processor status register (PS) after a reset are undefined, except for the interrupt disable flag (I) which is "1". After a reset, initialize flags which affect program execution. In particular, it is essential to initialize the index X mode (T) and the decimal mode (D) flags because of their effect on calculations.

Interrupts

The contents of the interrupt request bits do not change immediately after they have been written. After writing to an interrupt request register, execute at least one instruction before performing a BBC or BBS instruction.

Decimal Calculations

• To calculate in decimal notation, set the decimal mode flag (D) to "1", then execute an ADC or SBC instruction. After executing an ADC or SBC instruction, execute at least one instruction before executing a SEC, CLC, or CLD instruction.
• In decimal mode, the values of the negative (N), overflow (V), and zero (Z) flags are invalid.

Timers

If a value n (between 0 and 255) is written to a timer latch, the frequency division ratio is $1/(n+1)$.

Multiplication and Division Instructions

• The index X mode (T) and the decimal mode (D) flags do not affect the MUL and DIV instruction.
• The execution of these instructions does not change the contents of the processor status register.

Ports

The contents of the port direction registers cannot be read. The following cannot be used:
• The data transfer instruction (LDA, etc.)
• The operation instruction when the index X mode flag (T) is "1"
• The addressing mode which uses the value of a direction register as an index
• The bit-test instruction (BBC or BBS, etc.) to a direction register
• The read-modify-write instructions (ROR, CLB, or SEB, etc.) to a direction register.

Use instructions such as LDM and STA, etc., to set the port direction registers.

Serial I/O

In clock synchronous serial I/O, if the receive side is using an external clock and it is to output the $\overline{\text{SRDY}}$ signal, set the transmit enable bit, the receive enable bit, and the $\overline{\text{SRDY}}$ output enable bit to "1".
Serial I/O continues to output the final bit from the TxD pin after transmission is completed.

A-D Converter

The comparator is constructed linked to a capacitor. When the conversion speed is not enough, the conversion accuracy might be ruined by the disappearance of the charge. When A-D conversion is performed, set f(XIN) to at least 500 kHz.
When the following operations are performed, the A-D conversion operation cannot be guaranteed.
•When the CPU mode register is operated during A-D conversion operation,
•When the A-D control register is operated during A-D conversion operation,
•When STP or WIT instruction is executed during A-D conversion operation.

Instruction Execution Time

The instruction execution time is obtained by multiplying the frequency of the internal clock ϕ by the number of cycles needed to execute an instruction.
The number of cycles required to execute an instruction is shown in the list of machine instructions.

LCD Control

When using the voltage multiplier, apply prescribed voltage to the VLIN pin in the state in which the LCD enable bit is "0", and set the voltage multiplier enable bit to "1".

NOTES ON USE
Countermeasures Against Noise

(1) Shortest wiring length

① Wiring for $\overline{\text{RESET}}$ pin
Make the length of wiring which is connected to the $\overline{\text{RESET}}$ pin as short as possible. Especially, connect a capacitor across the $\overline{\text{RESET}}$ pin and the Vss pin with the shortest possible wiring (within 20mm).

● Reason
The width of a pulse input into the $\overline{\text{RESET}}$ pin is determined by the timing necessary conditions. If noise having a shorter pulse width than the standard is input to the $\overline{\text{RESET}}$ pin, the reset is released before the internal state of the microcomputer is completely initialized. This may cause a program runaway.
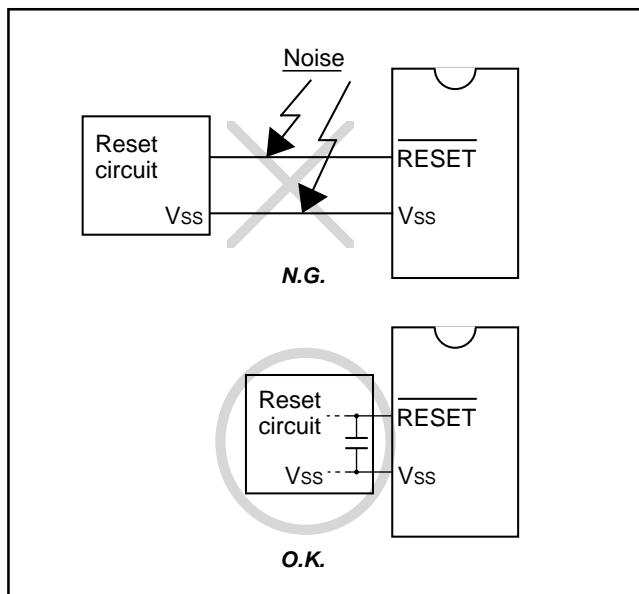
Fig. 40 Wiring for the $\overline{\text{RESET}}$ pin

② Wiring for clock input/output pins
• Make the length of wiring which is connected to clock I/O pins as short as possible.
• Make the length of wiring (within 20 mm) across the grounding lead of a capacitor which is connected to an oscillator and the Vss pin of a microcomputer as short as possible.
• Separate the Vss pattern only for oscillation from other Vss patterns.

● Reason
If noise enters clock I/O pins, clock waveforms may be deformed. This may cause a program failure or program runaway. Also, if a potential difference is caused by the noise between the Vss level of a microcomputer and the Vss level of an oscillator, the correct clock will not be input in the microcomputer.
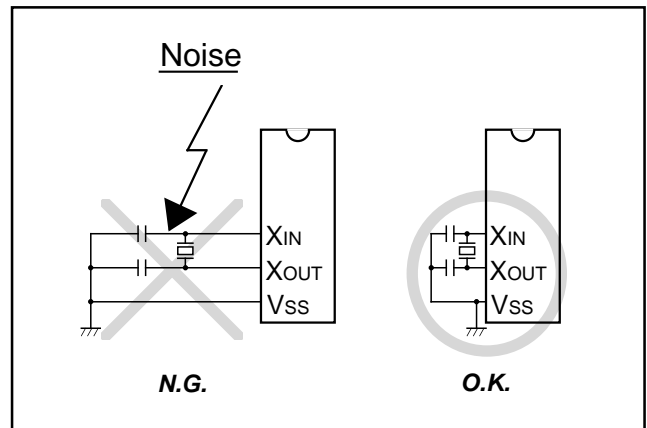
Fig. 41 Wiring for clock I/O pins

(2) Connection of bypass capacitor across Vss line and Vcc line
In order to stabilize the system operation and avoid the latch-up, connect an approximately 0.1 μF bypass capacitor across the Vss line and the Vcc line as follows:
• Connect a bypass capacitor across the Vss pin and the Vcc pin at equal length.
• Connect a bypass capacitor across the Vss pin and the Vcc pin with the shortest possible wiring.
• Use lines with a larger diameter than other signal lines for Vss line and Vcc line.
• Connect the power source wiring via a bypass capacitor to the Vss pin and the Vcc pin.
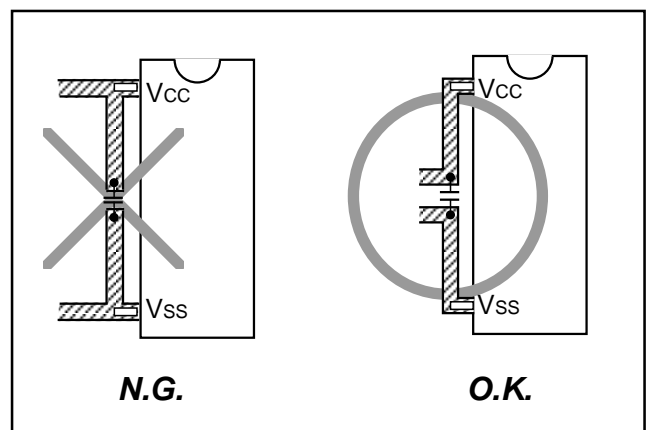
Fig. 42 Bypass capacitor across the Vss line and the Vcc line

(3) Oscillator concerns

In order to obtain the stabilized operation clock on the user system and its condition, contact the oscillator manufacturer and select the oscillator and oscillation circuit constants. Be careful especially when range of voltage or/and temperature is wide.

Also, take care to prevent an oscillator that generates clocks for a microcomputer operation from being affected by other signals.

① Keeping oscillator away from large current signal lines

Install a microcomputer (and especially an oscillator) as far as possible from signal lines where a current larger than the tolerance of current value flows.

● Reason

In the system using a microcomputer, there are signal lines for controlling motors, LEDs, and thermal heads or others. When a large current flows through those signal lines, strong noise occurs because of mutual inductance.

② Installing oscillator away from signal lines where potential levels change frequently

Install an oscillator and a connecting pattern of an oscillator away from signal lines where potential levels change frequently. Also, do not cross such signal lines over the clock lines or the signal lines which are sensitive to noise.

● Reason

Signal lines where potential levels change frequently (such as the CNTR pin signal line) may affect other lines at signal rising edge or falling edge. If such lines cross over a clock line, clock waveforms may be deformed, which causes a microcomputer failure or a program runaway.
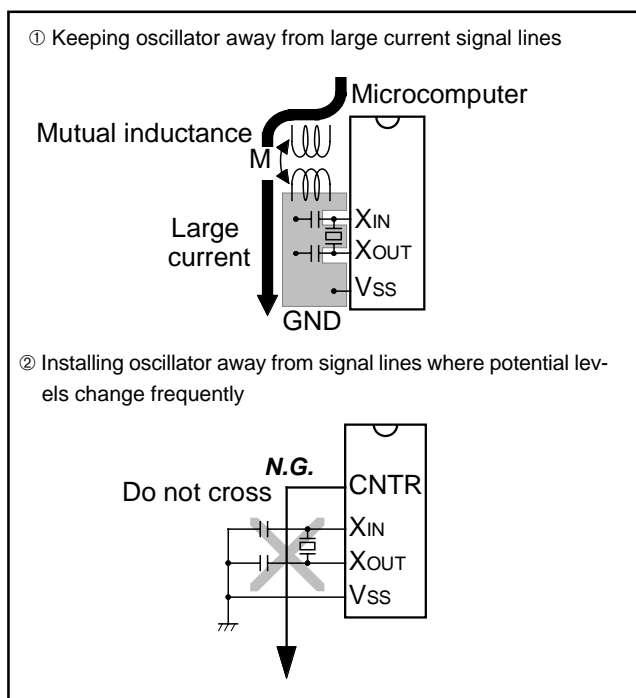
Fig. 43 Wiring for a large current signal line/Wiring of signal lines where potential levels change frequently

(4) Analog input

The analog input pin is connected to the capacitor of a comparator. Accordingly, sufficient accuracy may not be obtained by the charge/discharge current at the time of A-D conversion when the analog signal source of high-impedance is connected to an analog input pin. In order to obtain the A-D conversion result stabilized more, please lower the impedance of an analog signal source, or add the smoothing capacitor to an analog input pin.

(5) Difference of memory type and size

When Mask ROM and PROM version and memory size differ in one group, actual values such as an electrical characteristics, A-D conversion accuracy, and the amount of proof of noise incorrect operation may differ from the ideal values.

When these products are used switching, perform system evaluation for each product of every after confirming product specification.

(6) Wiring to V_{PP} pin of One Time PROM version

Connect an approximately 5 kΩ resistor to the V_{PP} pin the shortest possible in series.

Note: Even when a circuit which included an approximately 5 kΩ resistor is used in the Mask ROM version, the microcomputer operates correctly.

● Reason

The V_{PP} pin of the One Time PROM version is the power source input pin for the built-in PROM. When programming in the built-in PROM, the impedance of the V_{PP} pin is low to allow the electric current for writing flow into the built-in PROM. Because of this, noise can enter easily. If noise enters the V_{PP} pin, abnormal instruction codes or data are read from the built-in PROM, which may cause a program runaway.
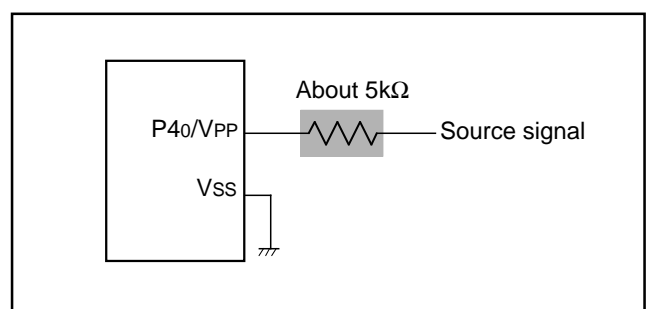
Fig. 44 Wiring for the V_{PP} pin of One Time PROM

DATA REQUIRED FOR MASK ORDERS

The following are necessary when ordering a mask ROM production:

1. Mask ROM Order Confirmation Form✽
2. Mark Specification Form✽
3. Data to be written to ROM, in EPROM form (three identical copies) or one floppy disk.

✽For the mask ROM confirmation and the mark specifications, refer to the "Mitsubishi MCU Technical Information" Homepage (http://www.infomicom.maec.co.jp/indexe.htm).

ROM PROGRAMMING METHOD

The built-in PROM of the blank One Time PROM version and built-in EPROM version can be read or programmed with a general-purpose PROM programmer using a special programming adapter (PCA7447FP).

Table 10 Programming adapter

Package	Name of Programming Adapter
144P6Q-A	PCA7447FP

The PROM of the blank One Time PROM version is not tested or screened in the assembly process and following processes. To ensure proper operation after programming, the procedure shown in Figure 45 is recommended to verify programming.

Programming with PROM programmer

↓

Screening (Caution)
(150°C for 40 hours)

↓

Verification with
PROM programmer

↓

Functional check in
target device

Caution : The screening temperature is far higher than the storage temperature. Never expose to 150 °C exceeding 100 hours.
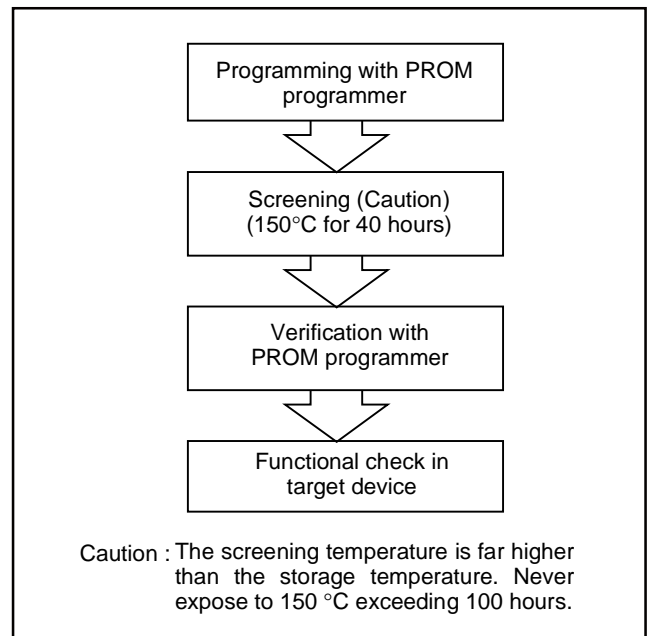
Fig. 45 Programming and testing of One Time PROM version

ELECTRICAL CHARACTERISTICS

Table 11 Absolute maximum ratings

Symbol	Parameter		Conditions	Ratings	Unit
V_{CC}	Power source voltage			−0.3 to 7.0	V
V_I	Input voltage	P0$_0$–P0$_7$, P1$_0$–P1$_7$, P2$_0$–P2$_7$, P3$_0$–P3$_3$, P4$_0$–P4$_7$	All voltages are based on Vss. Output transistors are cut off.	−0.3 to V_{CC}+0.3	V
V_I	Input voltage	C$_1$, C$_2$		−0.3 to 7.0	V
V_I	Input voltage	$\overline{RESET}$, X$_{IN}$, X$_{CIN}$		−0.3 to V_{CC}+0.3	V
V_I	Input voltage	V$_{LIN}$	When voltage multiplier is not operated.	−0.3 to 7.0	V
V_I	Input voltage	V$_{L1}$, V$_{L2}$, V$_{L3}$, V$_{L4}$, V$_{L5}$	V$_{L1}$≤V$_{L2}$≤V$_{L3}$≤V$_{L4}$≤V$_{L5}$	−0.3 to 7.0	V
V_O	Output voltage	P0$_0$–P0$_7$, P1$_0$–P1$_7$, P2$_0$–P2$_7$, P3$_0$–P3$_3$, P4$_1$–P4$_7$		−0.3 to V_{CC}+0.3	V
V_O	Output voltage	C$_1$, C$_2$, C$_3$		−0.3 to 7.0	V
V_O	Output voltage	COM$_0$–COM$_{31}$, SEG$_0$–SEG$_{67}$		−0.3 to V$_{L5}$+0.3	V
V_O	Output voltage	X$_{OUT}$, X$_{COUT}$		−0.3 to V_{CC}+0.3	V
P_d	Power dissipation		Ta = 25°C	300	mW
T_{opr}	Operating temperature			−20 to 85	°C
T_{stg}	Storage temperature			−40 to 125	°C

Table 12 Recommended operating conditions (Vcc = 2.2 to 5.5 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
V_{CC}	Power source voltage	High-speed mode f(X$_{IN}$) ≤ 8 MHz	4.0	5.0	5.5	V
		Middle-speed mode f(X$_{IN}$) ≤ 8 MHz	2.7	5.0	5.5	V
		Middle-speed mode (mask ROM version) f(X$_{IN}$) ≤ 4 MHz	2.2	5.0	5.5	V
		Middle-speed mode (One Time PROM version) f(X$_{IN}$) ≤ 4 MHz	2.5	5.0	5.5	V
		Low-speed mode (mask ROM version)	2.2	5.0	5.5	V
		Low-speed mode (One Time PROM version)	2.5	5.0	5.5	V
V_{SS}	Power source voltage			0		V
V_{LIN}	Power source voltage	V$_{LIN}$			2.33	V
V_{L5}	Power source voltage	V$_{L5}$			7.0	V
V_{IA}	Analog input voltage	A$_{IN0}$–A$_{IN7}$	Vss		Vcc	V
V_{IH}	"H" input voltage	P0$_0$–P0$_7$, P1$_0$–P1$_7$, P4$_5$, P4$_7$	0.7Vcc		Vcc	V
V_{IH}	"H" input voltage	P2$_0$–P2$_7$, P3$_0$–P3$_3$, P4$_0$–P4$_3$, P4$_4$, P4$_6$	0.8Vcc		Vcc	V
V_{IH}	"H" input voltage	$\overline{RESET}$	0.8Vcc		Vcc	V
V_{IH}	"H" input voltage	X$_{IN}$	0.8Vcc		Vcc	V
V_{IL}	"L" input voltage	P0$_0$–P0$_7$, P1$_0$–P1$_7$, P4$_5$, P4$_7$	Vss		0.3Vcc	V
V_{IL}	"L" input voltage	P2$_0$–P2$_7$, P3$_0$–P3$_3$, P4$_0$–P4$_3$, P4$_4$, P4$_6$	Vss		0.2Vcc	V
V_{IL}	"L" input voltage	$\overline{RESET}$	Vss		0.2Vcc	V
V_{IL}	"L" input voltage	X$_{IN}$	Vss		0.2Vcc	V
$\Sigma I_{OH(peak)}$	"H" total peak output current All ports **(Note 1)**				−60.0	mA
$\Sigma I_{OL(peak)}$	"L" total peak output current All ports **(Note 1)**				60.0	mA
$\Sigma I_{OH(avg)}$	"H" total average output current All ports **(Note 2)**				−30.0	mA
$\Sigma I_{OL(avg)}$	"L" total average output current All ports **(Note 2)**				30.0	mA
$I_{OH(peak)}$	"H" peak output current All ports **(Note 3)**				−5.0	mA
$I_{OL(peak)}$	"L" peak output current All ports **(Note 3)**				10.0	mA
$I_{OH(avg)}$	"H" average output current All ports **(Note 4)**				−2.5	mA
$I_{OL(avg)}$	"L" average output current All ports **(Note 4)**				5.0	mA
R_{OSC}	Oscillation resistor at selecting RC oscillation		5	8.2	10	kΩ

Notes 1: The total peak output current is the peak value of the peak currents flowing through all the applicable ports.
     2: The total average output current is the average value measured over 100 ms flowing through all the applicable ports.
     3: The peak output current is the peak current flowing in each port.
     4: The average output current is an average value measured over 100 ms.

RENESAS
RenesasTechnology Corp.

Table 13 Recommended operating conditions (mask ROM version) (Vcc = 2.2 to 5.5 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
$f(CNTR_0)$ $f(CNTR_1)$	Timer X, timer Y input frequency (duty cycle 50%)				$f(X_{IN})/2$	Hz
$f(X_{IN})$	Main clock input oscillation frequency **(Note 1)**	High-speed mode (4.0 V ≤ Vcc ≤ 5.5 V)			8.0	MHz
		High-speed mode (2.2 V ≤ Vcc < 4.0 V)			$2.9 \times Vcc - 3.6$	MHz
		Middle-speed mode (2.7 V ≤ Vcc ≤ 5.5 V)			8.0	MHz
		Middle-speed mode (2.2 V ≤ Vcc < 2.7 V)			$8 \times (Vcc - 1.7)$	MHz
$f(X_{CIN})$	Sub-clock input oscillation frequency **(Notes 1, 2)**			32.768	50	kHz

Notes 1: When the oscillation frequency has a duty cycle of 50 %.
2: When using the microcomputer in low-speed mode, set the sub-clock input oscillation frequency on condition that $f(X_{CIN}) < f(X_{IN})/3$.

Table 14 Recommended operating conditions (PROM version) (Vcc = 2.5 to 5.5 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
$f(CNTR_0)$ $f(CNTR_1)$	Timer X, timer Y input frequency (duty cycle 50%)				$f(X_{IN})/2$	Hz
$f(X_{IN})$	Main clock input oscillation frequency **(Note 1)**	High-speed mode (4.0 V ≤ Vcc ≤ 5.5 V)			8.0	MHz
		High-speed mode (2.5 V ≤ Vcc < 4.0 V)			$4 \times Vcc - 8$	MHz
		Middle-speed mode (2.7 V ≤ Vcc ≤ 5.5 V)			8.0	MHz
		Middle-speed mode (2.5 V ≤ Vcc < 2.7 V)			$20 \times (Vcc - 2.3)$	MHz
$f(X_{CIN})$	Sub-clock input oscillation frequency **(Notes 1, 2)**			32.768	50	kHz

Notes 1: When the oscillation frequency has a duty cycle of 50 %.
2: When using the microcomputer in low-speed mode, set the sub-clock input oscillation frequency on condition that $f(X_{CIN}) < f(X_{IN})/3$.

Table 15 Electrical characteristics (Vcc = 2.2 to 5.5 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V_{OH}	"H" output voltage P00–P07, P10–P17, P30–P33	I_{OH} = −5.0 mA VCC = 5.0 V	Vcc–2.0			V
		I_{OH} = −1.5 mA VCC = 5.0 V	Vcc–0.5			V
		I_{OH} = −1.25 mA VCC = 2.2 V	Vcc–1.0			V
V_{OH}	"H" output voltage P20–P27, P41–P47	I_{OH} = −5.0 mA VCC = 5.0 V	Vcc–2.0			V
		I_{OH} = −1.5 mA VCC = 5.0 V	Vcc–0.5			V
		I_{OH} = −1.25 mA VCC = 2.2 V	Vcc–1.0			V
V_{OL}	"L" output voltage P00–P07, P10–P17, P30–P33	I_{OL} = 5.0 mA VCC = 5.0 V			2.0	V
		I_{OL} = 1.5 mA VCC = 5.0 V			0.5	V
		I_{OL} = 1.25 mA VCC = 2.2 V			1.0	V
V_{OL}	"L" output voltage P20–P27, P41–P47	I_{OL} = 5.0 mA VCC = 5.0 V			2.0	V
		I_{OL} = 1.5 mA VCC = 5.0 V			0.5	V
		I_{OL} = 1.25 mA VCC = 2.2 V			1.0	V
V_{T+}–V_{T-}	Hysteresis INT0, INT1, ADT, CNTR0, CNTR1, P20–P27			0.5		V
V_{T+}–V_{T-}	Hysteresis S$_{CLK}$, RxD			0.5		V
V_{T+}–V_{T-}	Hysteresis $\overline{RESET}$			0.5		V
I_{IH}	"H" input current All ports				5.0	μA
I_{IH}	"H" input current $\overline{RESET}$				5.0	μA
I_{IH}	"H" input current X$_{IN}$			4.0		μA
I_{IL}	"L" input current All ports	V_I = Vss Pull-ups "off"			−5.0	μA
		VCC = 5.0 V, V_I = Vss Pull-ups "on"	−60.0	−120.0	−240.0	μA
		VCC = 2.2 V, V_I = Vss Pull-ups "on"	−5.0	−20.0	−40.0	μA
I_{IL}	"L" input current $\overline{RESET}$	V_I = Vss			−5.0	μA
I_{IL}	"L" input current X$_{IN}$	V_I = Vss		−4.0		μA

RENESAS
Renesas Technology Corp.

Table 16 Electrical characteristics (Vcc = 2.2 to 5.5 V, Ta = –20 to 85°C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V_{RAM}	RAM hold voltage	When clock is stopped	2.0	5.0	5.5	V
I_{CC}	Power source current	High-speed mode, Vcc = 5.0 V f(X_{IN}) = 8.0 MHz f(X_{CIN}) = 32.768 kHz		5.5	11.0	mA
		Middle-speed mode, Vcc = 5.0 V f(X_{IN}) = 8.0 MHz f(X_{CIN}) = 32.768 kHz		3.0	6.0	mA
		Middle-speed mode, Vcc = 3.0 V f(X_{IN}) = 8.0 MHz f(X_{CIN}) = 32.768 kHz		1.0	2.0	mA
		Low-speed mode, V_{CC} = 3.0 V, f(X_{IN}) = stopped f(X_{CIN}) = 32.768 kHz		20.0	40.0	µA
		High-/Middle-speed mode, V_{CC} = 5.0 V, f(X_{IN}) = 8.0 MHz (in WIT state) f(X_{CIN}) = 32.768 kHz		0.9	1.8	mA
		High-/Middle-speed mode, Vcc = 3.0 V f(X_{IN}) = 8.0 MHz (in WIT state) f(X_{CIN}) = 32.768 kHz		0.3	0.6	mA
		Low-speed mode, V_{CC} = 3.0 V, f(X_{IN}) = stopped f(X_{CIN}) = 32.768 kHz (in WIT state)		4.5	9.0	µA
		All oscillation stopped Ta = 25 °C, Output transistors "off" (in STP state)		0.1	1.0	µA
		All oscillation stopped Ta = 85 °C, Output transistors "off" (in STP state)			10.0	µA
I_{AD}	A-D converter current dissipation	Current increase at A-D converter operated, f(X_{IN}) = 8.0 MHz		0.8	1.6	mA
I_{L5}	V_{L5} input current **(Note)**	V_{L5} = 6.0 V, Ta = 25 °C		3	6	µA
F_{ROSC}	RC oscillation frequency	R_{OSC} = 8.2 kΩ	1.5	2.5	3.5	MHz

Note: When normal drivability (drivability selection bit 1 = "0", drivability selection bit 2 = "0") is selected.

Table 17 A-D converter characteristics

(Vcc = 2.2 to 5.5 V, Vss = 0 V, Ta = −20 to 85°C, f(XIN) ≤ 4 MHz, in middle-speed/high-speed mode)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution				10	Bits
—	Absolute accuracy	Vcc = 2.7–5.5 V			±4	LSB
	(excluding quantization error)	Vcc = 2.5–2.7 V (Ta = −10 to 50 °C)			±6	LSB
t_{conv}	Conversion time	f(XIN) = 4 MHz **(Note)**	30.5		34	µs
I_{IA}	Analog port input current			0.5	5.0	µA

Note: When main clock is selected as system clock.

Table 18 Timing requirements 1 (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
$t_w(\overline{RESET})$	Reset input "L" pulse width	2			µs
$t_c(X_{IN})$	Main clock input cycle time (XIN input)	125			ns
$t_{wH}(X_{IN})$	Main clock input "H" pulse width	45			ns
$t_{wL}(X_{IN})$	Main clock input "L" pulse width	40			ns
$t_c(CNTR)$	CNTR0, CNTR1 input cycle time	250			ns
$t_{wH}(CNTR)$	CNTR0, CNTR1 input "H" pulse width	105			ns
$t_{wL}(CNTR)$	CNTR0, CNTR1 input "L" pulse width	105			ns
$t_{wH}(INT)$	INT0, INT1 input "H" pulse width	80			ns
$t_{wL}(INT)$	INT0, INT1 input "L" pulse width	80			ns
$t_c(S_{CLK})$	Serial I/O clock input cycle time **(Note)**	800			ns
$t_{wH}(S_{CLK})$	Serial I/O clock input "H" pulse width **(Note)**	370			ns
$t_{wL}(S_{CLK})$	Serial I/O clock input "L" pulse width **(Note)**	370			ns
$t_{su}(RxD-S_{CLK})$	Serial I/O input setup time	220			ns
$t_h(S_{CLK}-RxD)$	Serial I/O input hold time	100			ns

Note: When bit 6 of address 001A16 is "1".
Divide this value by four when bit 6 of address 001A16 is "0".

Table 19 Timing requirements 2 (mask ROM version) (Vcc = 2.2 to 4.0 V, Vss = 0 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
$t_w(\overline{RESET})$	Reset input "L" pulse width	2			µs
$t_c(X_{IN})$	Main clock input cycle time (XIN input) Vcc = 2.7 to 4.0 V	125			ns
	Main clock input cycle time (XIN input) Vcc = 2.2 to 2.7 V	250			ns
$t_{wH}(X_{IN})$	Main clock input "H" pulse width Vcc = 2.7 to 4.0 V	45			ns
	Main clock input "H" pulse width Vcc = 2.2 to 2.7 V	100			ns
$t_{wL}(X_{IN})$	Main clock input "L" pulse width Vcc = 2.7 to 4.0 V	40			ns
	Main clock input "L" pulse width Vcc = 2.2 to 2.7 V	100			ns
$t_c(CNTR)$	CNTR0, CNTR1 input cycle time	2/f(XIN)			s
$t_{wH}(CNTR)$	CNTR0, CNTR1 input "H" pulse width	tc(CNTR)/2–20			ns
$t_{wL}(CNTR)$	CNTR0, CNTR1 input "L" pulse width	tc(CNTR)/2–20			ns
$t_{wH}(INT)$	INT0, INT1 input "H" pulse width	230			ns
$t_{wL}(INT)$	INT0, INT1 input "L" pulse width	230			ns
$t_c(S_{CLK})$	Serial I/O clock input cycle time **(Note)**	2000			ns
$t_{wH}(S_{CLK})$	Serial I/O clock input "H" pulse width **(Note)**	950			ns
$t_{wL}(S_{CLK})$	Serial I/O clock input "L" pulse width **(Note)**	950			ns
$t_{su}(RxD-S_{CLK})$	Serial I/O input setup time	400			ns
$t_h(S_{CLK}-RxD)$	Serial I/O input hold time	200			ns

Note: When bit 6 of address 001A16 is "1".
Divide this value by four when bit 6 of address 001A16 is "0".

Table 20 Timing requirements 2 (One Time PROM version) (Vcc = 2.5 to 4.0 V, Vss = 0 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
tw($\overline{\text{RESET}}$)	Reset input "L" pulse width		2			µs
tc(XIN)	Main clock input cycle time (XIN input) Vcc = 2.7 to 4.0 V		125			ns
	Main clock input cycle time (XIN input) Vcc = 2.5 to 2.7 V		250			ns
twH(XIN)	Main clock input "H" pulse width Vcc = 2.7 to 4.0 V		45			ns
	Main clock input "H" pulse width Vcc = 2.5 to 2.7 V		100			ns
twL(XIN)	Main clock input "L" pulse width Vcc = 2.7 to 4.0 V		40			ns
	Main clock input "L" pulse width Vcc = 2.5 to 2.7 V		100			ns
tc(CNTR)	CNTR0, CNTR1 input cycle time		2/f(XIN)			s
twH(CNTR)	CNTR0, CNTR1 input "H" pulse width		tc(CNTR)/2–20			ns
twL(CNTR)	CNTR0, CNTR1 input "L" pulse width		tc(CNTR)/2–20			ns
twH(INT)	INT0, INT1 input "H" pulse width		230			ns
twL(INT)	INT0, INT1 input "L" pulse width		230			ns
tc(SCLK)	Serial I/O clock input cycle time	**(Note)**	2000			ns
twH(SCLK)	Serial I/O clock input "H" pulse width	**(Note)**	950			ns
twL(SCLK)	Serial I/O clock input "L" pulse width	**(Note)**	950			ns
tsu(RxD-SCLK)	Serial I/O input setup time		400			ns
th(SCLK-RxD)	Serial I/O input hold time		200			ns

Note: When bit 6 of address 001A16 is "1".
      Divide this value by four when bit 6 of address 001A16 is "0".

Table 21 Switching characteristics 1 (Vcc = 4.0 to 5.5 V, Vss = 0 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
twH(SCLK)	Serial I/O clock output "H" pulse width		tc(SCLK)/2–30			ns
twL(SCLK)	Serial I/O clock output "L" pulse width		tc(SCLK)/2–30			ns
td(SCLK-TxD)	Serial I/O output delay time	**(Note 1)**			140	ns
tv(SCLK-TxD)	Serial I/O output valid time	**(Note 1)**	−30			ns
tr(SCLK)	Serial I/O clock output rising time				30	ns
tf(SCLK)	Serial I/O clock output falling time				30	ns
tr(CMOS)	CMOS output rising time	**(Note 2)**		10	30	ns
tf(CMOS)	CMOS output falling time	**(Note 2)**		10	30	ns

Notes 1: When the P45/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".
   2: The XOUT and XCOUT pins are excluded.

Table 22 Switching characteristics 2 (Vcc = 2.2 to 4.0 V, Vss = 0 V, Ta = −20 to 85°C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
twH(SCLK)	Serial I/O clock output "H" pulse width		tc(SCLK)/2–50			ns
twL(SCLK)	Serial I/O clock output "L" pulse width		tc(SCLK)/2–50			ns
td(SCLK-TxD)	Serial I/O output delay time	**(Note 1)**			350	ns
tv(SCLK-TxD)	Serial I/O output valid time	**(Note 1)**	−30			ns
tr(SCLK)	Serial I/O clock output rising time				50	ns
tf(SCLK)	Serial I/O clock output falling time				50	ns
tr(CMOS)	CMOS output rising time	**(Note 2)**		20	50	ns
tf(CMOS)	CMOS output falling time	**(Note 2)**		20	50	ns

Notes 1: When the P45/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is "0".
   2: The XOUT and XCOUT pins are excluded.

Measurement output pin
100 pF
CMOS output

1 kΩ
Measurement output pin
100 pF
N-channel open-drain output **(Note)**

Note: When bit 4 of the UART control register (address 001B16) is "1". (N-channel open-drain output mode)
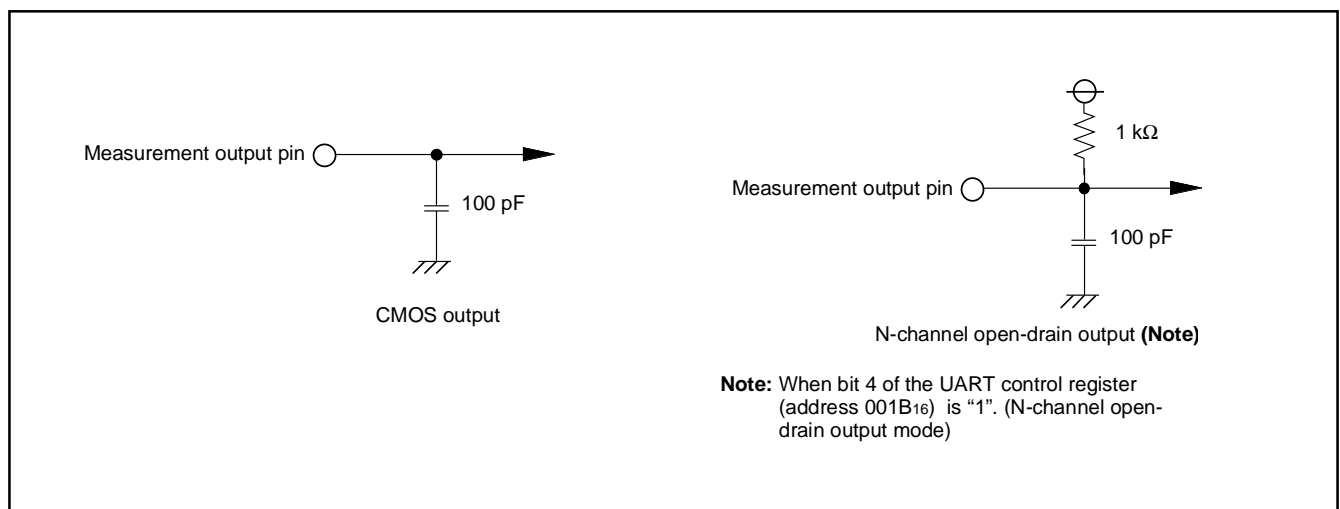
Fig. 46 Circuit for measuring output switching characteristics
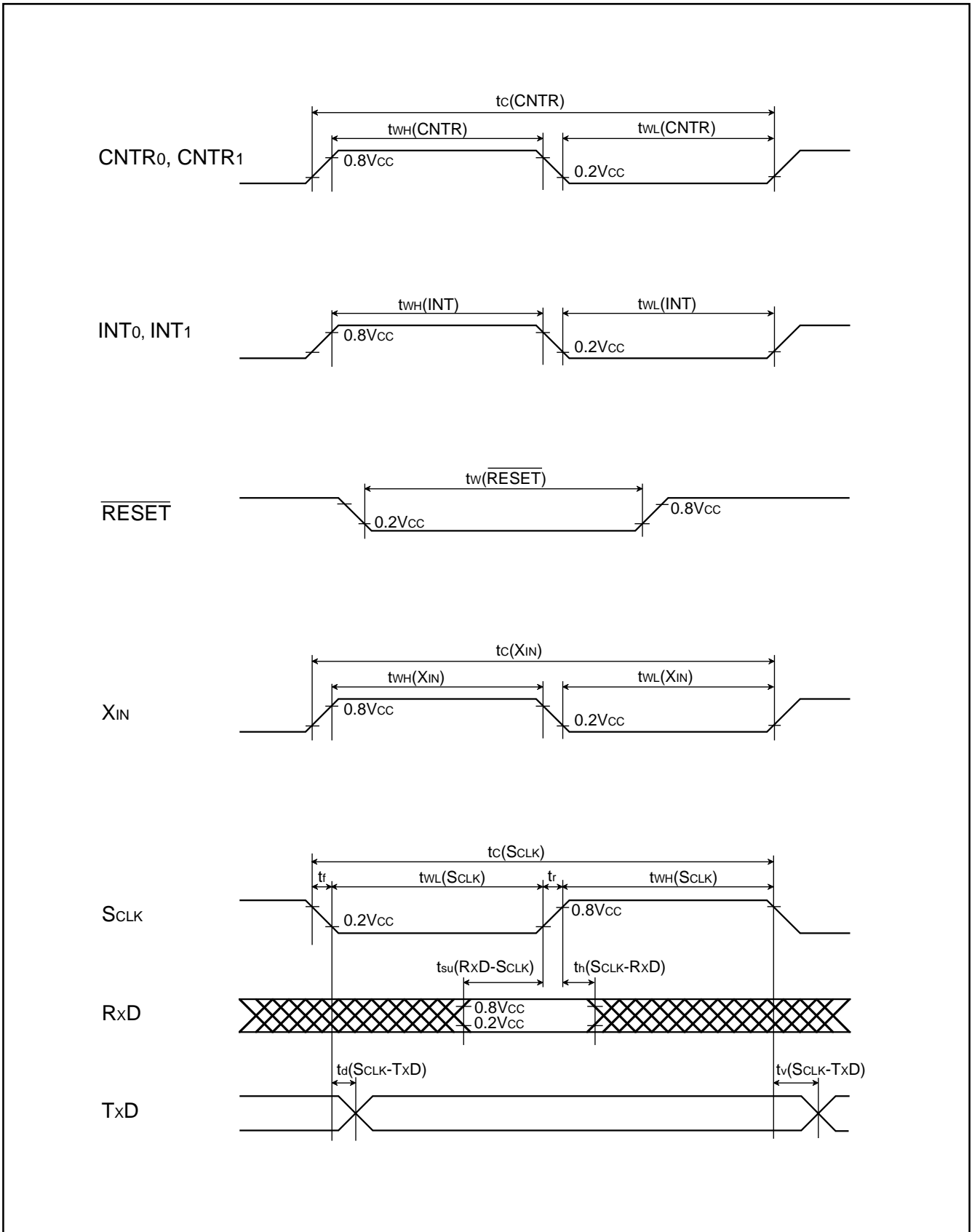
Fig. 47 Timing diagram

PACKAGE OUTLINE

144P6Q-A   (MMP)

Plastic 144pin 20×20mm body LQFP

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
LQFP144-P-2020-0.50	–	1.23	Cu Alloy

Recommended Mount Pad
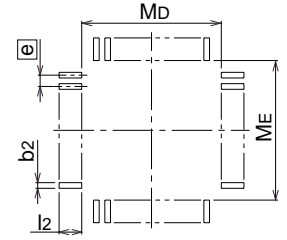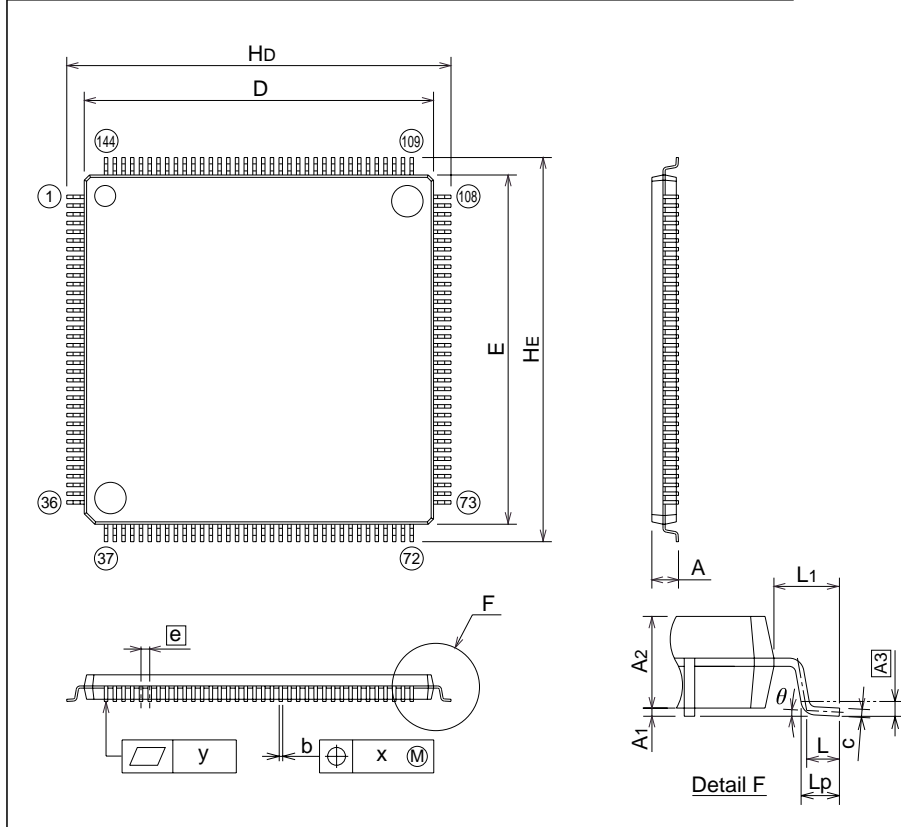
Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	–	–	1.7
A1	0.05	0.125	0.2
A2	–	1.4	–
b	0.17	0.22	0.27
c	0.105	0.125	0.175
D	19.9	20.0	20.1
E	19.9	20.0	20.1
e	–	0.5	–
HD	21.8	22.0	22.2
HE	21.8	22.0	22.2
L	0.35	0.5	0.65
L1	–	1.0	–
Lp	0.45	0.6	0.75
A3	–	0.25	–
x	–	–	0.08
y	–	–	0.1
θ	0°	–	8°
b2	–	0.225	–
I2	0.95	–	–
MD	–	20.4	–
ME	–	20.4	–

Detail F

Renesas Technology Corp.

Nippon Bldg.,6-2,Otemachi 2-chome,Chiyoda-ku,Tokyo,100-0004 Japan

RENESAS
Renesas Technology Corp.

REVISION HISTORY	38C8 GROUP DATA SHEET

Rev.	Date	Description		
		Page	Summary	
1.0	01/18/01		First Edition	
1.1	03/21/01	2 3 4 14 17 26 33 34 37 37 40 41 42 42	Figure 1 is partly revised. Figure 2 is partly revised. Pin name into Table 1 is partly revised. Pin name into Table 5 is partly revised. Explanations of "Interrupt Operation" are partly eliminated. Address of [Baud Rate Generator (BRG)] is revised. Figure name of Figure 31 is partly revised. Figure name of Figure 32 is partly revised. Explanations of "CLOCK GENERATING CIRCUIT" are partly revised. Explanations of "(1) Middle-speed Mode" of "Frequency Control" are partly revised. "At STP Instruction Release" is eliminated. Explanations of "DATA REQUIRED FOR MASK ORDERS" are partly revised. Pin name of V_{IA} into Table 11 is revised. Limits of V_{IH}, V_{IL} of P4$_0$, P4$_3$ are revised.	
1.2	10/15/01	3 15 16 41 42 43 43 43 43 43 46 46 47	Figure 2 is partly revised. Figure 11 is partly revised. Figure 12 is partly revised. Table 10 is added. Vcc parameter into Table 12 is partly eliminated. Unit of f(CNTR0), f(CNTR1) into Table 13 is revised. Limits of f(X_{IN}) in high-speed mode (2.2 V ≤ Vcc < 4.0 V) into Table 13 is revised. f(X_{IN}) in middle-speed mode (2.2 V ≤ Vcc < 2.7 V) into Table 13 is added. Unit of f(CNTR0), f(CNTR1) into Table 14 is revised. f(X_{IN}) in middle-speed mode (2.5 V ≤ Vcc < 2.7 V) into Table 14 is added. Limits of tc(X_{IN}), tWH(X_{IN}), tWL(X_{IN}) into Table 19 are added. Limits and unit of tc(CNTR) into Table 19 are revised. Table 20 is added.	
1.3	12/05/01	3 14 17 18 28 28 28 40	Figure 2 is partly revised. Table 5 is partly revised. Explanations of "■Notes on interrupts" are partly revised. Figure 14 is partly revised. Explanations of "[A-D Control Register (ADCON)]" are partly revised. Explanations of "Comparator and Control Circuit" are partly revised. Figure 25 is partly revised. Explanations of "A-D Converter" of "NOTES ON PROGRAMMING" are partly revised.	
1.4	06/25/02	All pages 1 3 4 6 8 9 10 11 14	Preliminary Notice in the header is eliminated. Interrupts of "[FEATURES]" are corrected. Figure 2 is partly revised. Pin COM0–COM15 in Table 1 is revised. Figure 4 is partly revised. Note in Figure 4 is partly revised. Explanations of bit 3 are added. Bit 4 name in Figure 7 is revised. Remarks in Figure 7 are partly revised. Table 5 is partly revised.	

Rev.	Date	Description		
		Page	Summary	
1.4	06/25/02	15	(1) in Figure 11 is partly revised.	
		17	Some source numbers in "[INTERRUPTS]" are corrected.	
		19	Figure 15 is partly revised.	
		20	The mode name (buzzer output mode) in Figure 16 is corrected.The mode name	
		20	of bit 6 in Figure 17 is corrected.	
		21	Explanations of "[(2) Buzzer Output Mode]" are partly added.	
		25	f(X_{CIN}) in Figure 22 is added.	
		30	Explanations of "[LC2]" are partly revised.	
		31	Explanations of "[Bias Control]" and "[Voltage Multiplier]" are partly revised.	
		31	Table 8 is partly revised.	
		32	Explanations of "[LCD Display RAM]" is partly revised.	
		35	Note in Figure 33 is eliminated.	
		37	Explanations of "[(1) Stop Mode]" is partly revised.	
		38	Note in Figure 38 is partly revised.	
		39	Bit 4 name in Figure 39 is revised.	
		40	Explanations of "[A-D Converter]" is partly revised.	
		41, 42	"[NOTES ON USE]" is added.	
		44	Table 12 is partly revised.	
		46	Table 15 is partly revised.	
		47	Table 16 is partly revised.	
1.5	10/23/02	15	(3), (4) and (5) in Figure 11 are partly revised.	